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# **IEEE Std 1149.1 (JTAG) Testability**

*Primer*



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Printed in U.S.A.  
1096-AL

SSYA002D

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Device Boundary-Scan Description Language (BSDL) files and other information regarding Texas Instruments IEEE Std 1149.1/JTAG/boundary-scan products are maintained on the World-Wide Web at URL <http://www.ti.com/sc/docs/jtag/jtaghome.htm>; or, on the main Texas Instruments home page at URL <http://www.ti.com>. Search for keywords JTAG and testability.







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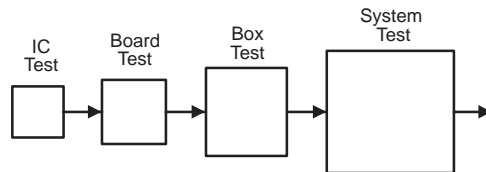
## Chapter 1 Introduction

*Design for test (DFT)*, also known as *design for testability*, is a process that incorporates rules and techniques in the design of a product to make testing easier.

Structured design for test is a system methodology rather than a collection of discrete techniques. This methodology impacts all phases of a product's life, from device circuit design through field service. Design for test is used to manage complexity, minimize development time, and reduce manufacturing costs.

Testing has two major aspects: control and observation. To test any system it is necessary to put the system into a known state, supply known input data (test data), and observe the system to see if it performs as designed and manufactured. If control or observation cannot be carried out, there is no way to know empirically if the system performs as it should.

During the normal product development flow, testing (it may be known by different names) takes place at many points during the process. If testing is considered at the chip design level, its benefits can be used at all levels of electronic assembly, from chip through system level. See Figure 1-1.



**Figure 1-1. Chip Through System-Level Test**

Designers usually test various functions to validate their design. Manufacturing and customer groups subject the design to an assortment of unique criteria to see if the concept works in practice. Is it manufacturable? Will it stand up to real-world operating conditions? Will repair be cost efficient? In addition to direct testability considerations, production managers want features designed into the product to help them minimize scrap and manufacturing costs. Good system-testability methodology provides an integrative function throughout the product development cycle and allows materials created during an early phase of development to be reused in later phases. Various chip designers have used this integration feature as a tool to help manage the development of complex products.

Testability provides companies with a firmer grasp on the economic and market-window constraints due to product development. One major workstation manufacturer claimed:

- Test program development would have been nearly impossible without scan techniques.
- Chip-level test development time fell from 1 man-year to about 20 hours.
- Board-level test development time fell from multiple man-years to about a week.
- Three months were cut off development time.

### **Overall Rationale for Design for Test**

Manufacturers of state-of-the-art electronic products face a unique set of problems. Although modern circuit density, high device speed, surface-mount packaging, and complex board-interconnect technology have a positive influence on state-of-the-art electronic systems, these factors can adversely affect ability to verify correct design and operation. Increased complexity and lack of physical access to circuitry makes for costly and time-consuming testing using traditional test techniques.

### Reduced Cost and Higher Quality

Reacting to this complexity, with an eye on the bottom line, manufacturers may opt to perform less rigorous testing. Manufacturers who choose the less rigorous testing as an expeditious alternative to the expense of full testing gamble their technical credibility in the marketplace and expose themselves to the high cost of product returns. In today's global electronics marketplace, a manufacturer who delivers poorly tested products does not remain competitive. The cost for detecting and identifying faults using traditional test methods increases by an order of magnitude as a circuit's level of complexity increases. These increased costs and development time reduce profit margins, delay product introduction, and reduce time-to-market windows. An increasing number of companies have simultaneously improved their product quality and profit margins by adopting system-level (integrative) design methods. Design for test is one such system-level approach.

### Benefits Over Standard Test Methods

Time to market is more important than ever in the high technology marketplace. Companies that can produce quality products with a short product development cycle-time have a competitive advantage. Designing testability into a system can play an important role in introducing a new high-technology product with an expected five-year life cycle to market on time. Table 1-1 shows various product development time/budget scenarios and the resulting project profitability.

**Table 1-1. High-Technology Product Scenarios †**

	Product A	Product B	Product C
<i>To Market:</i>	on time	on time	6 mos. late
<i>Budget:</i>	on	50% over	on
<i>Available Profit Over 5 Years:</i>	100%	96%	66%

†Source:McKinsey & Company

Adding testability to a product increases design time and costs, while reducing costs of design validation, manufacturing test, and system maintenance.

The system design phase of product development represents only 15 percent of a product's total life-cycle cost. However, the system design phase has a 70-percent impact on a product's operation and support costs over the product's total life (source: Mitre Corporation, 1987 Government Microcircuit Applications Conference).

The majority of faults found on boards, such as solder joints (shorts and opens), components (wrong device, missing device, wrong orientation, wire-bond failure, and stuck pins), etch integrity, and connector faults, make up over 95 percent of failures found. A structured technique such as boundary-scan testing allows for pins-out testing to easily detect these failures (source: Teradyne).

The additional cost of designing testability into a system during the system design phase can be more than offset over the product's total life.

Design cycle times have shortened significantly over the years while test program development time has increased, necessitating that companies adopt structured or repeatable methodologies. Table 1-2 documents the increase in test program development time as test requirements increase.

**Table 1-2. Time to Develop Test Programs (in Man-Months)†**

1987–1980	3–6 months
1981–1983	6–12 months
1984–1986	9–18 months
1987–1990	12–24 months

†Source: Texas Instruments



## Standard Test Solutions Versus Proprietary Solutions

Embedded test, emulation, and maintenance circuitry are well defined and understood within the test community. Previously, the lack of standards caused these structures to be implemented in an *ad hoc* and proprietary manner. Since proprietary solutions are usually more expensive and labor intensive, the added costs further limited the use of these test circuits. Boundary-scan testing combined with a common test bus interface and test protocol has these benefits:

- Provides a standard and cost-effective solution to traditional test problems
- Opens new applications

The ability to reuse previously developed test data and to use less costly test equipment means that this approach yields products that are less expensive to manufacture.

## An Industry Standard — IEEE Std 1149.1-1990 (JTAG)

In 1985, an *ad hoc* group composed of key electronic manufacturers joined to form the Joint Test Action Group (JTAG). JTAG had over 200 members around the world, including major electronics and semiconductor manufacturers. This group met to establish a solution to the problems of board test and to promote a solution as an industry standard. The solution, which became IEEE Std 1149.1-1990, *IEEE Standard Test Access Port and Boundary-Scan Architecture*, is the basis for Texas Instruments (TI™) testability products. IEEE Std 1149.1 allows test instructions and data to be serially loaded into a device and enables the subsequent test results to be serially read out.

Every IEEE Std 1149.1-compatible device has four additional pins — two for control and one each for input and output serial test data. To be compatible, a component must have certain basic test features, but IEEE Std 1149.1 allows designers to add test features to meet their own unique requirements. The specification was adopted as an IEEE standard in February 1990.





## Chapter 2

### Benefits of Testability

This chapter explains how designing testability into devices eliminates problems associated with traditional testing and improves quality and efficiency.

#### **Traditional Testing**

Traditional board-level and device-level testing consumes a great deal of time and requires special hardware and complex automatic test equipment (ATE) for each type of board or device. This results in increased costs and development time. In addition, extensive testing is necessary for the evermore stringent reliability standards and performance standards in the defense, aerospace, automotive, computer, and communications industries. These extensive tests can delay the market introduction of products, disrupt just-in-time (JIT) manufacturing flows, and limit the productivity of standard ATE operations. This creates numerous problems because time to market is more important than ever in the high-technology marketplace. Companies that produce quality products with a short product-development cycle time have a competitive advantage.

#### **Efficient Testing**

An innovative approach to the problems inherent with traditional testing is to incorporate design-for-test techniques that allow embedded testing to be performed. For example, data can be scanned in to stimulate internal system nodes while the component or circuit is embedded within the system. During the same scan, the previous condition of each node is scanned out. This saves test time and reduces the number of test vectors needed.

#### **Lower Cost for Testing**

The additional cost of designing testability into a system during the design phase is more than offset over the product's total life. This is accomplished by reducing the test program development time, minimizing fixture complexity, and allowing for the use of lower-cost ATE solutions. Another cost benefit is the economy of scale gained by having a standard test approach that spans design, test, manufacture, field repairs, and maintenance.



### **Production Time Savings**

Board-level boundary-scan testing is easily implemented using TI's line of IEEE Std 1149.1 testability devices, such as:

- Widebus™ and octal bus interfaces
- Scan-support devices
- ASIC and DSP

These IEEE Std 1149.1-compliant devices are included in board design with little modification to existing circuitry. Embedded testability greatly reduces the need for other test points on the board, and offers these advantages:

- Greatly simplified test fixtures
- Reduced fixture construction time
- Sophisticated built-in test and debug operations

Many ICs or boards can be tested together using the serial IEEE Std 1149.1 test bus under the control of boundary-scan test software.

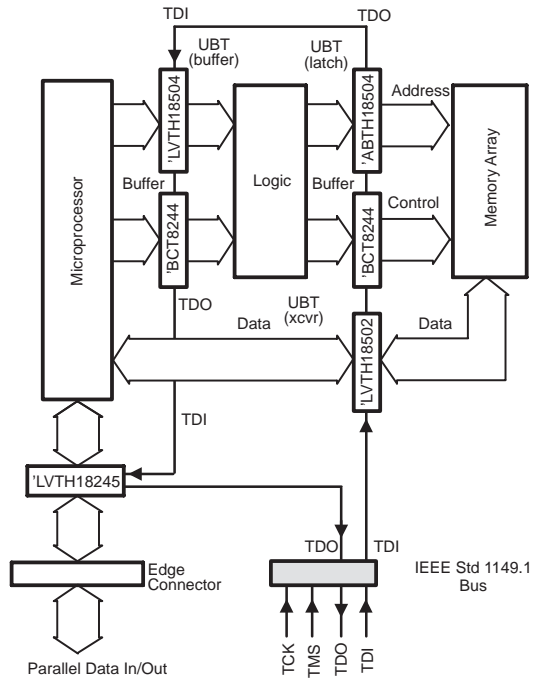
### **Easier Board-Level Isolation**

Fault isolation on a printed circuit board can be greatly improved by electronically isolating suspect areas using boundary-scannable devices. The IEEE Std 1149.1 test bus controls boundary-scannable devices to place them in *EXTEST* for pins-out testing. This effectively partitions or isolates circuitry for separate testing. Partitioning a system using IEEE Std 1149.1-compliant devices reduces the number of patterns required for testing each circuit area. See Figure 2-1 for an example of a design that can be partitioned.

### **Simple Access to Circuits**

Highly integrated, modern, multilayer systems or ICs with fine-pitch pins are virtually impossible to access using manual probes or ATE. Some boards require extensive fixturing or redesign before they can be tested effectively. TI's testability devices with boundary-scan architecture eliminate physical access problems. These parts provide the designer with testability for the most complex and hard-to-access circuits, and add controllability of test circuits. In addition, a designer can easily observe and control internal device functions.





**Figure 2-1. Boundary-Scan Testing Using the IEEE Std 1149.1 Bus**



## **Chapter 3**

### **Boundary-Scan Architecture and IEEE Std 1149.1**

Boundary scan is a special type of scan path with a register added at every I/O pin on a device. Although this requires the addition of a special test latch on some pins, the technique offers several important benefits. The most obvious benefit offered by the boundary-scan technique is allowing fault isolation at the component level. Such an isolation requirement is common in telecommunications switching environments where prompt field repair is critical.

A major problem driving the development of IEEE Std 1149.1 boundary scan is the adverse effect of surface-mount technology. The inclusion of a boundary-scan path in surface-mount components, in many cases, affords the only way to perform continuity tests between devices. By placing a known value on an output buffer of one device and observing the input buffer of another interconnected device, it is easy to see if the printed wiring board (PWB) net is electrically connected. Failure of this simple test indicates broken circuit traces, cold solder joints, solder bridges, or electrostatic-discharge (ESD) induced failures in an IC buffer — all common problems on PWBs.

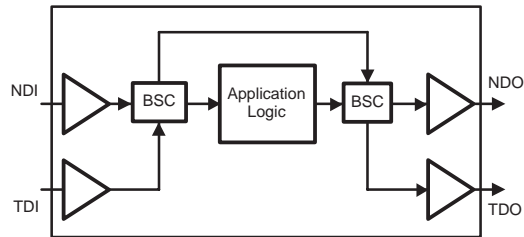
A less-obvious advantage of the boundary-scan methodology is the ability to apply predeveloped functional pattern sets to the I/O pins of the IC by way of the scan path. IC manufacturers and ASIC developers create functional pattern sets for DC test purposes. Subsets of these patterns can be reused for in-circuit functional IC testing. Reusing existing patterns in the development of system diagnostics can save large amounts of development resources, especially if many of the ICs in a system have embedded boundary-scan paths.

IEEE Std 1149.1 is a common protocol and boundary-scan architecture developed into an industrial standard after thousands of man hours of cooperative development by approximately 200 major international electronics firms. Early contributors in the development of IEEE Std 1149.1 were AT&T, DEC™, Ericsson, IBM™, Nixdorf, Philips, Siemens, and TI. These companies recognized that only a nonproprietary architecture would encourage companies to

offer the compatible integrated circuits, test equipment, and CAD software needed to bring product development, manufacturing, and test costs under control in today's competitive electronics marketplace. Many people believe that boundary-scan architecture will do for development, manufacturing, and test what the RS-232C standard did for computer peripherals.


### Boundary-Scan Overview

Boundary scan is the application of a scan path at the boundary (I/O) of ICs to provide controllability and observability access via scan operations. Figure 3-1 shows an IC with an application-logic section and related input and output, and a boundary-scan path consisting of a series of boundary-scan cells (BSCs), in this case one BSC per IC function pin.



**Figure 3-1. Boundary-Scan Example**

The BSCs are interconnected to form a scan path between the host IC's test data input (TDI) pin and test data output (TDO) pin. During normal IC operation, input and output signals pass freely through each BSC, from the normal data input (NDI), to the normal data output (NDO). However, when the boundary-test mode is entered, the IC's boundary is controlled in such a way that test stimulus can be shifted in and applied from each BSC output (NDO), and test response can be captured at each BSC input (NDI) and shifted out for inspection. External testing of wiring interconnects and neighboring ICs on a board assembly is accomplished by applying test stimulus from the output BSCs and capturing test response at the input BSCs. As an option, internal testing of the application logic can be accomplished by

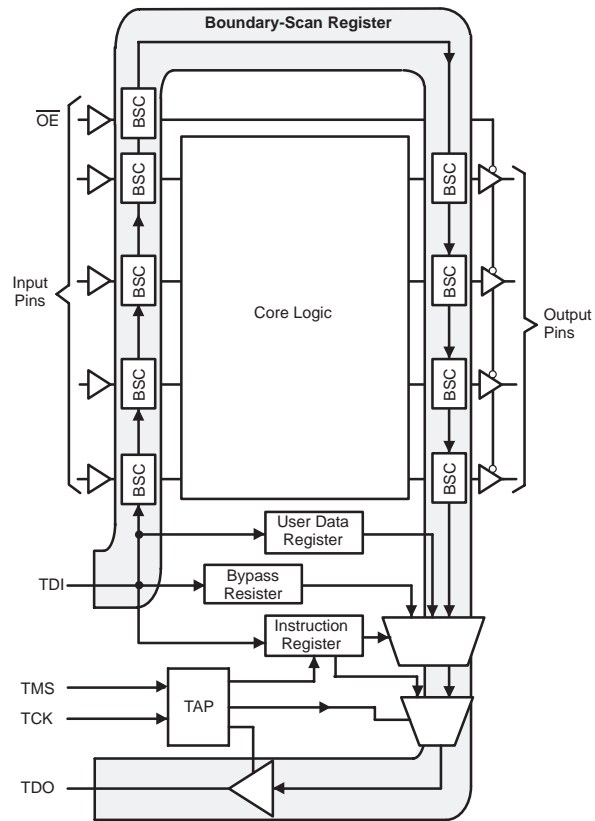


applying test stimulus from the input BSCs and capturing test response at the output BSCs. The implementation of a scan path at the boundary of IC designs provides an embedded testing capability that can overcome the physical access problems in current and future board designs.

### **Test Interface and Boundary-Scan Architecture**

Figure 3-2 shows the IEEE Std 1149.1 architecture. The architecture consists of an instruction register, a bypass register, a boundary-scan register (highlighted), optional user data register(s), and a test interface referred to as the test access port (TAP). In Figure 3-2, the boundary-scan register (BSR), a serially accessed data register made up of a series of boundary-scan cells (BSCs), is shown at the input and output boundary of the IC.

The instruction register and data registers are separate scan paths arranged between the primary test data input (TDI) pin and primary test data output (TDO) pin. This architecture allows the TAP to select and shift data through one of the two types of scan paths, instruction or data, without accessing the other scan path.

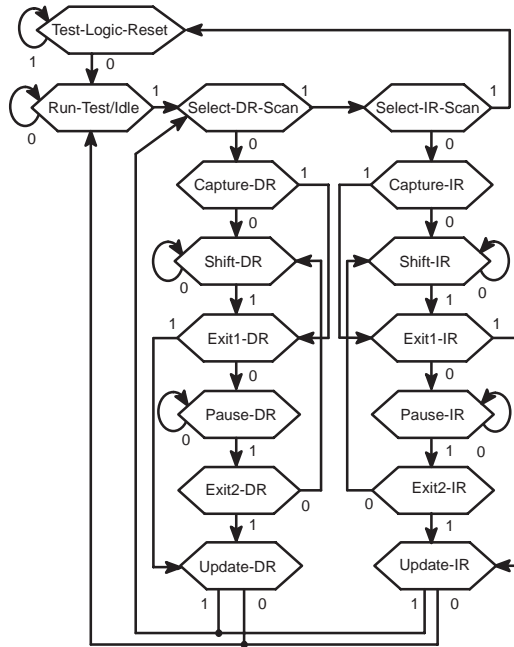


Note: The boundary-scan register is shifted TDI to TDO.

**Figure 3-2. Boundary-Scan Architecture**

### Test Access Port and Operation

The TAP is controlled by the test clock (TCK) and test mode select (TMS) inputs. These two inputs determine whether an instruction register scan or data register scan is performed. The TAP consists of a small controller design, driven by the TCK input, which responds to the TMS input as shown in the state diagram in Figure 3-3. The IEEE Std 1149.1 test bus uses both clock edges of TCK. TMS and TDI are sampled on the rising edge of TCK, while TDO changes on the falling edge of TCK.



Note: The value shown adjacent to each state transition in this figure represents the signal present at TMS at the rising edge of TCK.

Figure 3-3. TAP Controller State Diagram

The main state diagram consists of six steady states: Test-Logic-Reset, Run-Test/Idle, Shift-DR, Pause-DR, Shift-IR, and Pause-IR. A unique feature of this protocol is that only one steady state exists for the condition when TMS is set high: the Test-Logic-Reset state. This means that a reset of the test logic can be achieved within five TCKs or less by setting the TMS input high.

At power up, or during normal operation of the host IC, the TAP is forced into the Test-Logic-Reset state by driving TMS high and applying five or more TCKs. In this state, the TAP issues a reset signal that places all test logic in a condition that does not impede normal operation of the host IC. When test access is required, a protocol is applied via the TMS and TCK inputs, causing the TAP to exit the Test-Logic-Reset state and move through the appropriate states. From the Run-Test/Idle state, an instruction register scan or a data register scan can be issued to transition the TAP through the appropriate states shown in Figure 3-3.

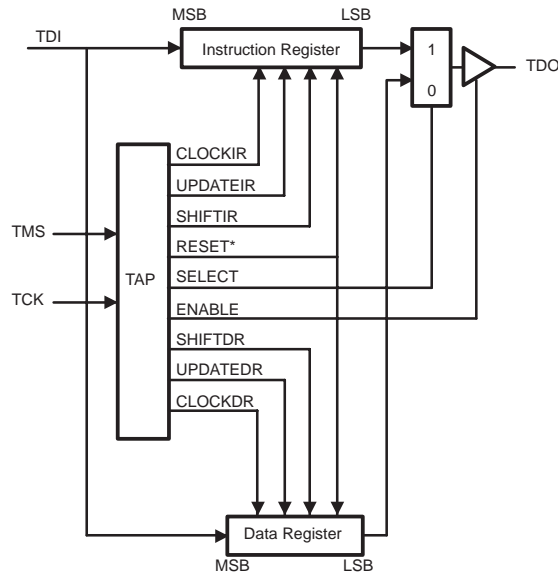
The states of the data register scan and instruction register scan blocks are mirror images of each other, adding symmetry to the protocol sequences. The first action that occurs when either block is entered is a capture operation. For the data registers, the Capture-DR state is used to capture (or parallel load) the data into the selected serial data path. If the BSR is the selected data register, the normal data inputs (NDIs) are captured during this state. In the instruction register, the Capture-IR state is used to capture status information into the instruction register.

From the Capture state, the TAP transitions to either the Shift or Exit1 state. Normally, the Shift state follows the Capture state so that test data or status information can be shifted out for inspection and new data shifted in. Following the Shift state, the TAP either returns to the Run-Test/Idle state via the Exit1 and Update states or enters the Pause state via Exit1. The reason for entering the Pause state is to temporarily suspend the shifting of data through either the selected data register or instruction register while a required operation, such as refilling a tester memory buffer, is performed. From the Pause state, shifting can resume by re-entering the Shift state via the Exit2 state or be terminated by entering the Run-Test/Idle state via the Exit2 and Update states.



Upon entering the data register scan or instruction register scan blocks, shadow latches in the selected scan path are forced to hold their present state during the capture and shift operations. The data being shifted into the selected scan path is not output through the shadow latch until the TAP enters the Update-DR or Update-IR state. The Update state causes the shadow latches to update (or parallel load) with the new data that has been shifted into the selected scan path.

Figure 3-4 shows the TAP control output signals, along with the instruction register and data register interconnects.



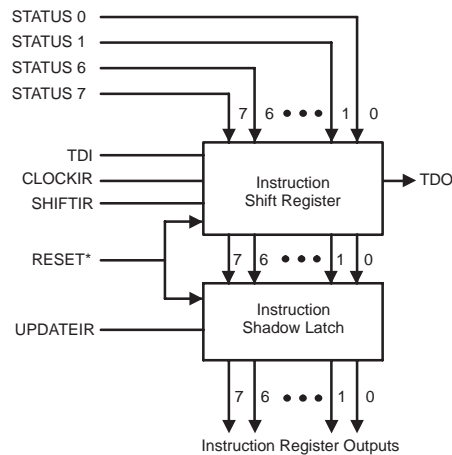
**Figure 3-4. TAP Control Output Interconnect Diagram**

## IEEE Std 1149.1 Registers

This section contains descriptions of the required and optional registers specified in IEEE Std 1149.1-1990.

### *Instruction Register (Required)*

The instruction register is responsible for providing the address and control signals required to access a particular data register in the scan path. The instruction register is accessed when the TAP receives an instruction register scan protocol. During an instruction register scan operation the SELECT output from the TAP (Figure 3-4) selects the output of the instruction register to drive the TDO pin. A general instruction register architecture is shown in Figure 3-5.



**Figure 3-5. General Instruction Register Architecture**

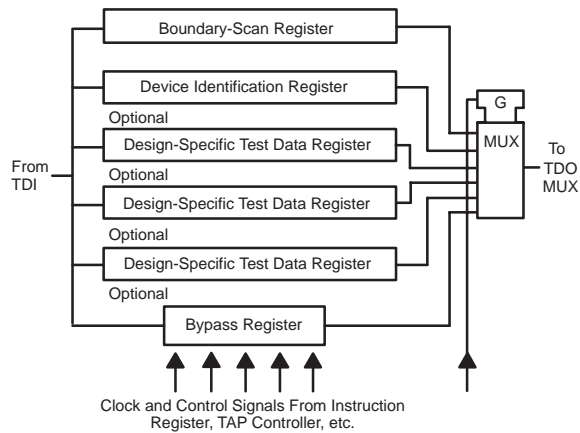
The instruction register consists of an instruction shift register and an instruction shadow latch. The instruction shift register (Figure 3-5) consists of a series of shift register bits arranged to form a single scan path between the TDI and TDO pins of the host IC. During instruction register scan operations, the TAP exerts control via the instruction register shift enable (SHIFDIR) and instruction register clock

(CLOCKIR) signals to cause the instruction shift register to preload status information and shift data from TDI to TDO. Both the preload and shift operations occur on the rising edge of TCK; however, the data shifted out from the host IC from TDO occurs on the falling edge of TCK. The status inputs are user-defined observability inputs, except for the two least-significant bits, which are always 01 for scan-path testing purposes. (The instruction register has a minimum length of two bits.)

The instruction shadow register (Figure 3-5) consists of a series of latches, one latch for each instruction shift register bit. During an instruction register scan operation, the latches remain in their present state. At the end of the instruction register scan operation, the instruction register update (UPDATEIR) input updates the latches with the new instruction installed in the instruction shift register. When activated, the RESET\* input sets the instruction shadow register to the value of the *BYPASS* instruction (or *IDCODE* instruction, if it is supported). This forces the device into its normal functional mode and selects the bypass register (or device identification register, if one is present).

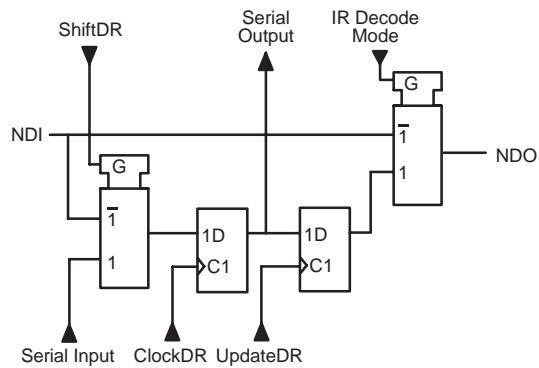
#### **Data Registers**

IEEE Std 1149.1 requires two data registers; boundary-scan register and bypass register, with a third, optional, device identification register. Additional user-defined data registers can be included. The data registers are arranged in parallel from the primary TDI input to the primary TDO output. The instruction register supplies the address that allows one of the data registers to be accessed during a data register scan operation. During a data register scan operation, the addressed scan register receives TAP control via the data register shift enable (SHIFTDR) and data register clock (CLOCKDR) inputs to preload test response and shift data from TDI to TDO. During a data register scan operation, the SELECT output from the TAP (Figure 3-4) selects the output of the data register to drive the TDO pin. When one scan path in the data register is being accessed, all other scan paths remain in their present state.



**Figure 3-6. Test Data Register Architecture**

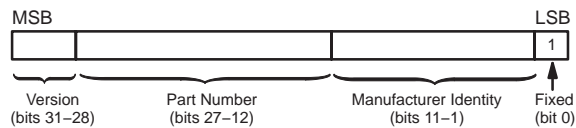
*Boundary-Scan Register* — The boundary-scan register (BSR) consists of a series of boundary-scan cells (BSCs) arranged to form a scan path around the boundary of the host IC. The BSCs provide the controllability and observability features required to perform boundary-scan testing as described in the *Boundary-Scan Overview* section of this chapter. Shadow latches in the BSCs, driving the NDO outputs remain in their present state during a data register scan operation. At the end of a data register scan operation, the data register update (UPDATEDR) input updates the shadow latches with the new boundary test pattern to be applied from the NDO outputs of the BSCs. Figure 3-7 shows a conceptual view of a control-and-observe BSC.



**Figure 3-7. Conceptual View of a Control-and-Observe BSC**

**Bypass Register (Required)** — The bypass register consists of a single scan register bit. When selected, the bypass register provides a single-bit scan path between TDI and TDO. Thus, the bypass register allows abbreviating the scan path through devices that are not involved in the test. The bypass register is selected when the instruction register is loaded with a pattern of all ones to satisfy the IEEE Std 1149.1 *BYPASS* instruction requirement.

**Device Identification Register (Optional)** — The device identification register is an optional register, defined by IEEE Std 1149.1, to identify the device's manufacturer, part number, revision, and other device-specific information. Figure 3-8 shows the bit assignments defined for the device identification register. These bits can be scanned out of the device identification register after its selection.



**Figure 3-8. Device Identification Register Structure**

Although the device identification register is optional, IEEE Std 1149.1 has dedicated an instruction to select

this register. The device identification register is selected when the instruction register is loaded with the *IDCODE* instruction, the bit code of which is defined by the vendor.

Manufacturer's identity codes (bit1 through bit11) are assigned, maintained, and updated by the EIA/JEDEC office. Any company can be added to the *JEDEC Standard Manufacturer's Identification Code* (Publication JEP106) by request to the JEDEC office at 202-457-4973.

### **IEEE Std 1149.1 Required Instructions**

IEEE Std 1149.1 defines nine test instructions. Of the nine instructions, three are required and six are optional. The following subsections contain brief descriptions of each required test instruction.

#### ***BYPASS Instruction***

The required *BYPASS* instruction allows the IC to remain in a functional mode and selects the bypass register to be connected between TDI and TDO. The *BYPASS* instruction allows serial data to be transferred through the IC from TDI to TDO without affecting the operation of the IC. The bit code of this instruction is defined as all ones by IEEE Std 1149.1.

#### ***SAMPLE/PRELOAD Instruction***

The required *SAMPLE/PRELOAD* instruction allows the IC to remain in its functional mode and selects the boundary-scan register to be connected between TDI and TDO. During this instruction, the boundary-scan register can be accessed via a data scan operation, to take a sample of the functional data entering and leaving the IC. This instruction is also used to preload test data into the boundary-scan register before loading an *EXTEST* instruction. The bit code for this instruction is defined by the vendor.



### ***EXTEST Instruction***

The required *EXTEST* instruction places the IC into an external boundary-test mode and selects the boundary-scan register to be connected between TDI and TDO. During this instruction, the boundary-scan register is accessed to drive test data off-chip via the boundary outputs and receive test data off-chip via the boundary inputs. The bit code of this instruction is defined as all zeroes by IEEE Std 1149.1.

### **IEEE Std 1149.1 Optional Instructions**

The following subsections contain brief descriptions of the optional IEEE Std 1149.1 instructions.

### ***INTEST Instruction***


The optional *INTEST* instruction places the IC in an internal boundary-test mode and selects the boundary-scan register to be connected between TDI and TDO. During this instruction, the boundary-scan register is accessed to drive test data on-chip via the boundary inputs and receive test data on-chip via the boundary outputs. The bit code of this instruction is defined by the vendor.

### ***RUNBIST Instruction***

The optional *RUNBIST* instruction places the IC in a self-test mode, enables a comprehensive self-test of the IC's core logic, and selects a user-specified data register to be connected between TDI and TDO. During this instruction, the boundary outputs are controlled so that they cannot interfere with neighboring ICs during the *RUNBIST* operation. Also, the boundary inputs are controlled so that external signals cannot interfere with the *RUNBIST* operation. The bit code of this instruction is defined by the vendor.

### ***CLAMP Instruction***

The optional *CLAMP* instruction sets the outputs of an IC to logic levels determined by the contents of the boundary-scan register and selects the bypass register to be connected between TDI and TDO. Before loading this instruction, the contents of the boundary-scan register can be preset with the *SAMPLE/PRELOAD* instruction. During this instruction, data can be shifted through the bypass register from TDI to



TDO without affecting the condition of the outputs. The bit code of this instruction is defined by the vendor.

***HIGHZ Instruction***

The optional *HIGHZ* instruction sets all outputs (including two-state as well as three-state types) of an IC to a disabled (high-impedance) state and selects the bypass register to be connected between TDI and TDO. During this instruction, data can be shifted through the bypass register from TDI to TDO without affecting the condition of the IC outputs. The bit code of this instruction is defined by the vendor.

***IDCODE Instruction***

The optional *IDCODE* instruction allows the IC to remain in its functional mode and selects the optional device identification register to be connected between TDI and TDO. The device identification register (see Figure 3-8) is a 32-bit shift register containing information regarding the IC manufacturer, device type, and version code. Accessing the device identification register does not interfere with the operation of the IC. Also, access to the device identification register should be immediately available, via a TAP data-scan operation, after power-up of the IC or after the TAP has been reset using the optional TRST\* pin or by otherwise moving to the Test-Logic-Reset state. The bit code of this instruction is defined by the vendor.

***USERCODE Instruction***

The optional *USERCODE* instruction allows the IC to remain in its functional mode and selects the device identification register to be connected between TDI and TDO. During the *USERCODE* instruction, the optional 32-bit device identification register captures user-defined information about the IC. Accessing the device identification register does not interfere with the operation of the IC. The bit code of this instruction is defined by the vendor.





### **Obtaining IEEE Std 1149.1-1990**

To learn more about IEEE Std 1149.1, please refer to the publications, *IEEE Standard Test Access Port and Boundary-Scan Architecture*, IEEE Std 1149.1-1990 (includes IEEE Std 1149.1a-1993) and *Supplement to IEEE Std 1149.1-1990, IEEE Standard Test Access Port and Boundary-Scan Architecture*, IEEE Std 1149.1b-1994. These documents are available through IEEE (1-800-678-IEEE). IEEE Std 1149.1-1990/IEEE Std 1149.1a-1993 is also available from Texas Instruments on CD-ROM (see Chapter 9, *Other Support and Learning Products*).





## Chapter 4 Using DFT in ASICs

The concern most often voiced by application-specific integrated circuit (ASIC) users is that of testability. This chapter is intended to provide an understanding of ASIC testability that can be used for developing test strategies when designs are being initiated.

### Design-for-Test Considerations

Designing testability into any circuit affects the hardware to some degree. Additional logic will probably have to be added. This additional logic increases the amount of silicon required to implement the design. The savings from enhanced testability do not usually show up until the cycle time and testing cost of the circuit and its end system are analyzed.

Fault simulation is an important part of designing for testability. This technique enables you to evaluate your test patterns to determine whether these patterns detect faults. Faults may occur during either the design-tooling stage or the circuit-fabrication stage. A fault simulator uses fault models, such as a node shorted to power (stuck-at-one) or a node shorted to ground (stuck-at-zero), and compares the response of a fault-free circuit with the response of a faulty circuit. If the response of the fault-free circuit is different than the response of the faulty circuit, then the test patterns have detected the fault.

By faulting all the nodes in the circuit, the fault simulator produces the test-pattern fault grade or fault coverage. The fault coverage is the percentage of faults detected among the total faults. The higher the fault coverage, the better the test pattern set separates a faulty circuit from a fault-free circuit. After determining which faults have not been detected by the current set of test patterns, additional test patterns can be generated to detect those faults.

Adoption of design-for-test principles early in the design process ensures the maximum testability for the minimum effort. These guidelines emphasize that test is a part of the design flow, not a process that is done at the end of the design cycle.

Three basic elements must come together to make a successful ASIC circuit:

- Logic design, including schematic capture, library selection, synthesis, and simulation
- Logic testability, including fault-detection and test-application criteria within predefined cost and time-scale budgets
- Vendor's manufacturing capability, including processing and packaging

### **The Need for Testability**

Most engineers involved in the design of ASIC devices are familiar with the trade-offs between gate arrays, standard cells, and full custom devices. They are also familiar with the vendor selection process. The aspect of test capability and testability is often overlooked.

Testability could be ignored when typical designs were only a few thousand gates. These designs were implemented first and then turned over to a test engineer or to a vendor to create a test program for production. As design complexities increased, this approach to testing became futile. Successful high-density ASIC design and manufacturing demand that circuits be built with testability incorporated into the design process.

Although testability imposes additional constraints in the design phase, design verification and test can be unmanageable, if ignored until the design is completed and testability is handled as a postdesign insertion. In fact, the design constraints are overwhelmingly balanced by improved testability, which adds value to the device throughout manufacturing and system life.

### Test-Time Cost

Test cost, as it relates to time, is a simple calculation. Most commercial testers cost between \$2 million and \$3 million. Under normal circumstances, the tester depreciation, plant, operator, and support personnel costs are between 10 and 20 cents per test second.

Brute-force test approaches often generate a large number of test patterns. Since test patterns are run at multiple power-supply values and possibly at multiple temperatures, inefficient pattern sets can severely impact the test costs of a complex ASIC device.

### Time to Market

Surveys indicate that 40 percent of the development cycle time for an ASIC device is required for test insertion and test-pattern generation. This figure is expected to increase as device complexity increases. The intent of a design-for-test strategy is to achieve high fault-detection test programs in reduced time (Figure 4-1). The obvious cycle-time reductions result from designed-in testability (elimination of iterative redesigns resulting from poor design practices), and from automatic test-pattern generation (ATPG).

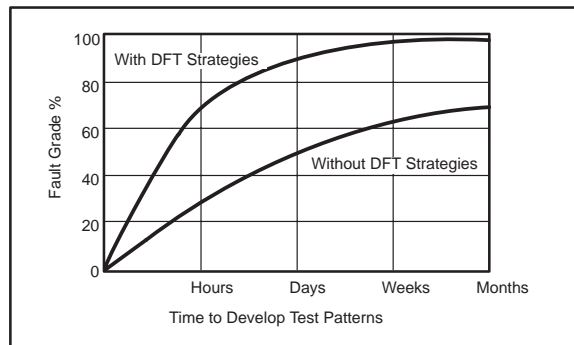
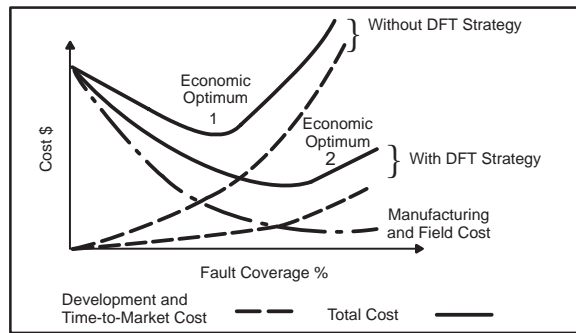


Figure 4-1. Fault Grade Versus Development Time

Figure 4-2 shows the economic relationship between time to market and system manufacturing and field maintenance costs. Point 1 represents the case where market-entry timing forces a constraint on the development time. Since 40 percent of this time is expended in inserting testability, the temptation is to rush to market with devices that are not completely testable or tested. The result is a higher-than-desirable manufacturing and field-maintenance cost. Point 2 represents the case where DFT and ATPG techniques are employed to develop devices that are completely tested. This situation allows an economic optimum that is more favorable to long-term manufacturing and maintenance costs.



**Figure 4-2. Economic Trade-Off for a Testable Design**

A less obvious result of a DFT strategy is the reduction of debug time. The designer must make certain assumptions about system requirements. Often, a new device does not work in the system environment and requires debugging. If the device is designed for controllability and observability access, the debugging process is enhanced. Conversely, if these two features are overlooked, debugging and manufacturing can be significantly harder to accomplish, if not impossible. Oscilloscopes and logic analyzers are not very effective in debugging systems utilizing complex ASIC devices in a surface-mount environment.

### Fault Coverage and Cost of Ownership

Figure 4-3 shows the trade-off between time to market and manufacturing and field-maintenance costs. The horizontal factor on this figure is fault coverage. The relationship between fault coverage and device defect level is well documented.

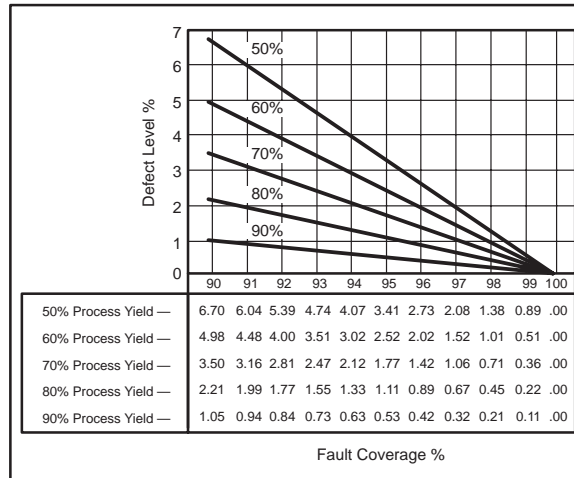
Figure 4-3 is a plot of the relationship modeled by T. W. Williams for fault coverages of 90 percent, or greater.

The Williams model is:

$$D = [1 - Y^{(1 - T)}] \times 100$$

Where:

- D = Defect level in percent
- Y = Theoretical functional process yield
- T = Fault coverage of the test program used



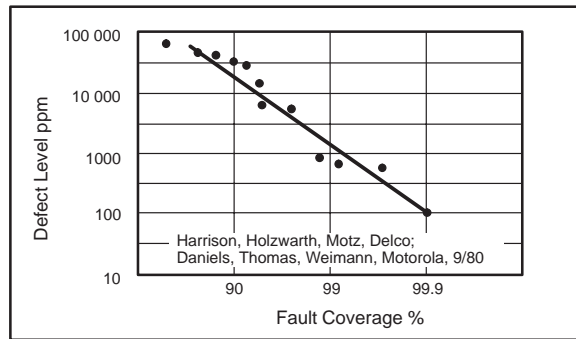
**Figure 4-3. Defect Level Versus Fault Coverage**

To briefly explore the Williams model, assume that the ASIC vendor has a silicon and assembly process yield that is

70 percent. If the fault grade of the test program is also 70 percent, the defect level is projected to be 10.1 percent, or 101,000 ppm (this is outside the limits of the chart and was calculated). At a fault grade of 90 percent, the defect level is projected to be 3.5 percent or 35,000 ppm.

A study of the model shows that the process yield becomes an insignificant term when the fault coverage of the test program is very close to 100 percent.

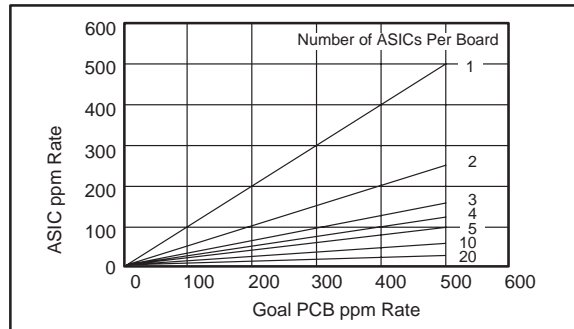
Motorola and Delco performed a study in 1980 that supports the Williams model. Their experimental results are shown in Figure 4-4. A fault coverage of 99.9 percent was required to obtain defect levels in the range of 100 ppm.



**Figure 4-4. Motorola and Delco Study Results**

Figure 4-5 shows the maximum allowable ASIC defect rate to achieve a goal PCB defect rate as a function of the number of ASIC devices per board assembly. Note that for multiple-device PCB designs, a goal of 500 ppm requires ASIC defect levels in the range of 100 to 200 ppm.





**Figure 4-5. ASIC ppm Versus PCB ppm Rate**

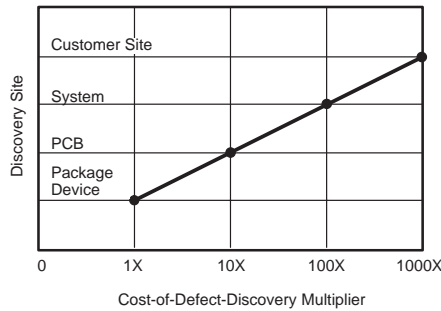
Theoretical and experimental studies conclude that a high-fault-grade test-pattern set is required for low-defect-level ASIC devices. This type of pattern set is nearly impossible to obtain through brute force. The requirements for a high-fault-grade pattern set are:

- ATPG tool
- Fault grader
- A testable design meeting the constraints of the ATPG tool

As stated earlier, a design-for-test strategy has performance and area costs. Now, the cost of new tools has been added. Benefits such as lower test costs and reduced time to market have been mentioned. These benefits are real, but often hard to quantify. Reduced cost of ownership is another major benefit and is easy to quantify.

Figure 4-6 shows what is commonly referred to as the "cost-of-ownership, order-of-magnitude relationship". It shows that each company has a cost associated with finding a defect in a packaged device before it has entered the assembly process. This cost can be calculated easily. The cost of finding a defective device after assembly onto a PCB is an order-of-magnitude more than before assembly. This continues until the cost to discover a defective device in a system at a customer's site is three orders-of-magnitude higher than that of discovery before assembly on to a PCB.

The lowest cost of ownership is achieved by finding defective units before they are shipped from the vendor.



**Figure 4-6. Cost of Ownership**

The previous discussions lead to the conclusion that the lowest cost of ownership can be obtained by providing the ASIC vendor with an efficient, high-fault-detection set of test vectors. These DFT methodologies provide lower cost of ownership with the added benefit of reduced time to market.

### Developing Testability Strategies

The following strategies outline the process of design for test.

1. Select a technology.  
When selecting a technology or vendor, make sure there is enough performance and gate-count margin to allow the insertion of testability.
2. Commit to testability design practices.  
Testability design practices work. Commit to use them, and review them with the design team before the design begins. Add a testability commitment to the design requirements document developed for the design project. Make testability audits part of the design review process.
3. Establish a fault-grade requirement.  
The fault-grade requirement usually can be provided by the manufacturing or quality organization. Establish this requirement before the first design review. Add the fault-grade requirement to the design requirements

document. This requirement drives many of the decisions that follow in the development of the test strategy.

Many companies consider the fault-grade requirement to be an index of device cost of ownership. Failure to achieve it impacts profits throughout the lifetime of the device.

4. Decide if IEEE Std 1149.1 is a system requirement.  
When implemented in an ASIC device, IEEE Std 1149.1 allows test of the interconnect between devices on a PCB through a four-pin test bus. If IEEE Std 1149.1 is selected, the four dedicated test pins also can be used to control core-logic test techniques such as built-in self-test (BIST), internal scan, on-chip emulation, and boundary-scan through the test access port (TAP) and instruction register.
5. Select an ASIC testability approach based on gate density.
  - Designs with fewer than 10K gates  
Designs with fewer than 10K gates are not generally complex enough to require structured test approaches. The overhead impact is usually too high to justify them. Nonstructured, good design practices are usually sufficient.
  - Designs with more than 10K gates, but fewer than 20K gates  
Structured techniques should be considered for designs in this density. Nonstructured, good design practices are probably sufficient for highly combinatorial circuits without memory. Structured approaches should be considered as complexity is increased by the addition of sequential circuits, feedback, and memory. Consider boundary-scan testing for reduced cycle times and high fault grades.
  - Designs with more than 20K gates  
The complexity of circuits this dense usually requires structured approaches to achieve high fault grades. At this density, it is often hard to control or observe deeply embedded circuits. The overhead associated with structured testability approaches is acceptable at this density.

6. Choose structured tools.

Scan testing is typically the preferred structured approach for sequential logic. The available scan choices are:

- Clocked scan
- Multiplexed flip-flop scan
- Level-sensitive scan-design (LSSD)
- Parallel scan chains
- Partial scan

7. Establish a diagnostic functional-pattern set to expedite debug.

This is an important step in decreasing the time to market for an ASIC device. The purpose of this pattern set is to isolate circuitry for analysis.

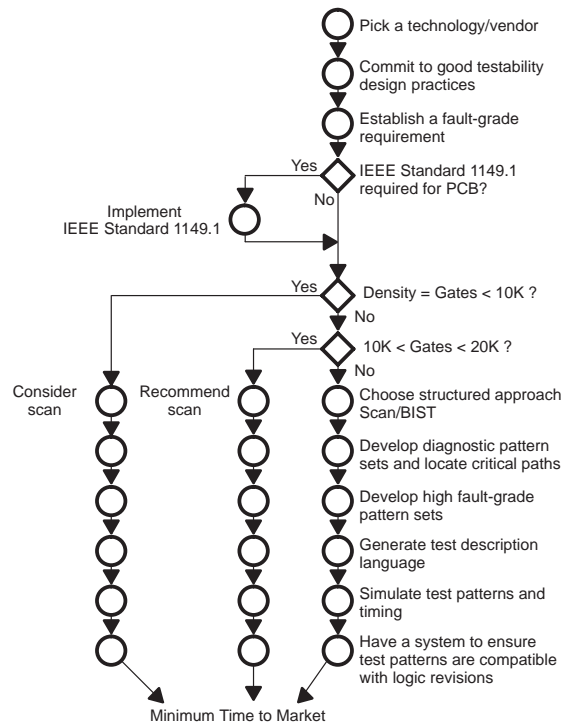
8. Generate high fault-grade test patterns.

The fault grade of a test pattern set determines the best possible quality level attainable with that set of patterns.

9. Simulate test patterns and timing.

Two types of simulation are required during development. Logic simulation verifies both functionality and performance of the device. Test-pattern simulation produces the information needed to verify the test patterns in a tester environment.

Figure 4-7 contains a flow chart that steps through the design-for-test process.



**Figure 4-7. Testability Development Flow**





## Chapter 5 Data Formats

Several data formats have emerged to make IEEE Std 1149.1 successful and well supported by tools. This chapter discusses the most widely accepted data formats that support IEEE Std 1149.1 — BSDL, HSDL, and SVF.

### **Boundary-Scan Description Language (BSDL)**

In 1990, IEEE Std 1149.1 was approved and implementation of the standard accelerated. As more people became aware of and used the standard, the need for a standard method for describing IEEE Std 1149.1-compatible devices was recognized. The IEEE Std 1149.1 working group established a subcommittee to develop a device description language to address this need.

The subcommittee has since developed an industry standard language called Boundary-Scan Description Language (BSDL). BSDL is a subset and standard practice of VHDL (VHSIC Hardware Description Language) that describes how IEEE Std 1149.1 is implemented in a device and how it operates. BSDL captures the essential features of any IEEE Std 1149.1 implementation. BSDL has been formally adopted as part of IEEE Std 1149.1b-1994.

IEEE Std 1149.1 is a structured design-for-test approach well suited for tools and automation. Tools developed to support the standard can control the test access port (TAP). If they know how the boundary-scan architecture was implemented in the device, such tools can also control the I/O of the device. BSDL provides a standard machine- and human-readable data format for describing how IEEE Std 1149.1 boundary-scan architecture is implemented in a device.

### ***How BSDL Is Used***

Many IEEE Std 1149.1 tools already on the market support BSDL as a data input format. These tools offer different capabilities to customers implementing IEEE Std 1149.1 into their designs, including board interconnect automatic test-pattern generation (ATPG) and automatic test equipment (ATE).

When tools that support BSDL are used, such BSDL is often received from the semiconductor vendor. This can result in significant time and cost savings.

Teradyne estimates that to create in-circuit test patterns for a leading microprocessor normally can take as long as seven weeks:

- One week to study the device
- Four weeks to develop in-circuit test patterns
- Two weeks to verify the patterns on ATE

The development cost estimate for this approach is \$14,000.

If the microprocessor supports IEEE Std 1149.1, and the BSDL is supplied by the vendor, the time to develop in-circuit test patterns is less than two hours (less than \$100) using today's tools.

#### ***Elements of BSDL***

A BSDL description for a device consists of the following elements:

- Entity descriptions
- Generic parameter
- Logical port description
- Use statement(s)
- Component conformance statement
- Pin mapping(s)
- Scan port identification
- Instruction register description
- Optional register description
- Register access description
- Boundary register description

*Entity Descriptions* — The entity statement names the entity, such as the device name (e.g., SN74BCT8245A). An entity description begins with an entity statement and terminates with an end statement.

```
entity XYZ is
  {statements to describe the entity go here}
end XYZ;
```



**Generic Parameter** — A generic parameter is a parameter that can come from outside the entity, or it can be defaulted, such as a package type (e.g., "DW").

```
generic (PHYSICAL_PIN_MAP : string := "DW");
```

**Logical Port Description** — The port description gives logical names to the I/O pins (system and TAP pins), and denotes their nature, such as input, output, bidirectional, linkage (analog or power supply/return) and so on.

```
port (OE:in bit;  
      Y:out bit_vector(1 to 3);  
      A:in bit_vector(1 to 3);  
      GND, VCC, NC:linkage bit;  
      TDO:out bit;  
      TMS, TDI, TCK:in bit);
```

**Use Statement(s)** — The use statement refers to external definitions found in packages and package bodies.

```
use STD_1149_1_1994.all;
```

**Component Conformance Statement** — The component conformance statement indicates the latest issue of IEEE Std 1149.1 to which the device conforms.

```
attribute COMPONENT_CONFORMANCE of XYZ : entity is  
  "STD_1149_1_1993";
```

**Pin Mapping(s)** — The pin mapping provides a mapping of logical signals onto the physical pins of a particular device package.

```
attribute PIN_MAP of XYZ : entity is  
  PHYSICAL_PIN_MAP;  
constant DW:PIN_MAP_STRING:=  
  "OE:1, Y:(2,3,4), A:(5,6,7), GND:8, VCC:9, " &  
  "TDO:10, TDI:11, TMS:12, TCK:13, NC:14";
```

**Scan Port Identification** — The scan port identification statements define the device's TAP.

```
attribute TAP_SCAN_IN of TDI : signal is TRUE;  
attribute TAP_SCAN_OUT of TDO : signal is TRUE;  
attribute TAP_SCAN_MODE of TMS : signal is TRUE;  
attribute TAP_SCAN_CLOCK of TCK : signal is (50.0e6,  
  BOTH);
```

**Instruction Register Description** — The instruction register description identifies the device-dependent characteristics of the instruction register.

```
attribute INSTRUCTION_LENGTH of XYZ : entity is 2;  
attribute INSTRUCTION_OPCODE of XYZ : entity is  
  "BYPASS (11)," &  
  "EXTEST (00)," &  
  "SAMPLE (10)," &  
  "IDCODE (01)";  
attribute INSTRUCTION_CAPTURE of XYZ : entity is  
  "01";
```

**Optional Register Description** — The optional register description identifies the values captured in the device identification register for the optional *IDCODE* and *USERCODE* instructions, if supported.

```
attribute IDCODE_REGISTER of XYZ : entity is
"01010100000011111100000000101111";
```

**Register Access Description** — The register access description defines which register is placed between TDI and TDO for each instruction.

```
attribute REGISTER_ACCESS of XYZ : entity is
"BOUNDARY (EXTEST, SAMPLE),"&
"BYPASS (BYPASS)";
```

**Boundary Register Description** — The boundary register description contains a list of boundary-scan cells, along with information regarding the cell type and associated control.

```
attribute BOUNDARY_LENGTH of XYZ : entity is 7;
attribute BOUNDARY_REGISTER of XYZ : entity is
"0 (BC_1, Y(1), output3, X, 6, 0, Z),"&
"1 (BC_1, Y(2), output3, X, 6, 0, Z),"&
"2 (BC_1, Y(3), output3, X, 6, 0, Z),"&
"3 (BC_1, A(1), input , X),"&
"4 (BC_1, A(2), input , X),"&
"5 (BC_1, A(3), input , X),"&
"6 (BC_1, OE , input , X),"&
"6 (BC_1, * , control, 0)";
```

#### **Verifying BSDL Accuracy**

Creating a BSDL file that is syntactically and semantically correct is only the beginning. A syntactically and semantically correct BSDL file can still contain descriptive errors and result in time-consuming debugging of board-level tests and diagnostics. A BSDL file must be validated (compared) against the silicon.

### **Potential BSDL Errors**

As with any hand-entered data, typographical errors potentially exist. BSDL contains many commas and semicolons that contribute error possibilities. Fortunately, syntax and semantics errors can easily be identified and corrected using syntax and semantics checking tools during the authoring process.

Other common errors are:

- Wrong pinout
- Wrong cell types
- Wrong boundary-scan register order
- Wrong boundary-scan register length
- Wrong instruction register opcodes
- Wrong control cell locations
- Wrong control cell disable value
- Wrong I/O pin control cell
- Wrong identification code value
- Wrong capture-IR value

Typographical errors or device documentation errors can result in implementation errors.

### **How to Receive the BSDL Specification**

Contact the IEEE (1-800-678-IEEE) and refer to *Supplement to IEEE Std 1149.1-1990, IEEE Standard Test Access Port and Boundary-Scan Architecture*, IEEE Std 1149.1b-1994 to receive a copy of the Boundary-Scan Description Language (BSDL) specification.

### **Obtaining BSDL for TI Devices**

Texas Instruments makes catalog-device BSDL files available to customers through the World-Wide Web. As of this writing, these files can be located on the Texas Instruments IEEE Std 1149.1/JTAG/Boundary-Scan Silicon Products page located at URL <http://www.ti.com/sc/docs/jtag/silicon.htm>; or, on the main Texas Instruments home page at URL <http://www.ti.com>. Search for keyword BSDL.

## **Hierarchical Scan Description Language (HSDL)**

Texas Instruments developed the hierarchical scan description language (HSDL) to complement BSDL, using the same subset of VHDL statements as BSDL. HSDL picks up where BSDL stops to describe additional attributes of IEEE Std 1149.1 devices and how IEEE Std 1149.1 devices are connected at the board and system levels.

HSDL uses the BSDL entity and package in new ways. Entities in HSDL are used to describe modules as well as devices. A module is any level of architecture above the device level, including boards, multichip modules, backplanes, subsystems, and systems. In addition, HSDL provides two new packages used to indicate that an entity is an HSDL device or module.

BSDL is ideal for describing how IEEE Std 1149.1 is implemented in a device, but stops there. HSDL provides a method for describing how IEEE Std 1149.1 devices are connected at the board, module, and system levels. HSDL serves two needs not addressed by BSDL:

- Describes the test-bus interconnections of IEEE Std 1149.1 at the board or module level
- Improves ease of use and reduces risk during interactive design debug and verification
- Allows descriptions of boards with dynamic and reconfigurable architectures

### ***Elements of HSDL***

HSDL module statements use much of the same syntax as BSDL. New statements have been added to describe the members and scan paths of the module and to simplify interactive use.

- Entity description
- Generic parameter
- Logical port description
- Use statement(s)
- [Optional module description(s)]
- [Optional port description(s)]
- Pin mapping(s)

- Scan port identification
- [Optional members description(s)]
- [Optional bus composition(s)]
- Path description
- [Optional member connections]
- [Optional constraint description(s)]
- [Optional design warning]

*Entity Description* — The entity statement names the entity, such as the module name (e.g., BOARD). An entity description begins with an entity statement and terminates with an end statement.

```
entity BOARD is
  {statements to describe the entity go here}
end BOARD;
```

*Generic Parameter* — A generic parameter may come from outside the entity or it may be defaulted, such as a package type (e.g., "UNDEFINED").

```
generic (PHYSICAL_PIN_MAP : string := "UNDEFINED");
```

*Logical Port Description* — The port description gives logical names to the I/O pins (system and TAP pins), and denotes their nature such as input, output, bidirectional, linkage (analog or power supply/return) and so on.

```
port (TDI:in bit;
      TDO:out bit;
      TMS:in bit;
      TCK:in bit;
      GND:linkage bit);
```

*Use Statement(s)* — The use statement refers to external definitions found in packages and package bodies.

```
use STD_1149_1_1994.all;
use HSDL_module.all;
```

*Pin Mapping(s)* — The pin mapping provides a mapping of logical signals onto the physical pins of a particular entity.

```
attribute PIN_MAP of BOARD : entity is
  PHYSICAL_PIN_MAP;
  constant PINOUT1 : PIN_MAP_STRING :=
    "TDI:1, TDO:2, TMS:3, TCK:4, GND:5";
```

*Scan Port Identification* — The scan port identification statements define the entity's TAP.

```
attribute TAP_SCAN_IN of TDI : signal is TRUE;
attribute TAP_SCAN_OUT of TDO : signal is TRUE;
attribute TAP_SCAN_MODE of TMS : signal is TRUE;
attribute TAP_SCAN_CLOCK of TCK : signal is (5.0e6,
LOW);
```

*Members Description (Optional)* — Members represent devices or other modules that are on the module. Usually members represent components, but some boards may contain scannable daughtercards, card slots, etc. that require member modules to describe them.

```
attribute MEMBERS of BOARD : entity is
"U1 (XYZ1, DW)," &
"U2 (XYZ2, DW)";
```

*Bus Composition (Optional)* — Buses in an HSDL module can be built of module buses, member module buses, member device buses, and member device test registers.

```
attribute BUS_COMPOSITION of BOARD : entity is
"bus1[4] (U1.Boundary[3,0])," &
"bus2[4] (U2.Boundary[3,0])";
```

*Path Description* — Module paths are intended to describe the netlist of TAP signals (scan paths) on the board.

```
constant boardpath1 : STATIC_PATH :=
"U1, U2";
end BOARD;
```

#### ***How to Receive the HSDL Specification***

Originally developed by Texas Instruments primarily in support of its ASSET business, HSDL is now supported by ASSET InterTech, which acquired ASSET™ in 1995.



## Serial Vector Format (SVF)

Serial Vector Format, commonly referred to as SVF, was jointly developed by Texas Instruments and Teradyne in 1991. SVF is a standard ASCII format for expressing test patterns that represent the stimulus, expected response, and mask data for IEEE Std 1149.1-based tests. The need for SVF arose from the desire to have vendor-independent IEEE Std 1149.1 test patterns that are transportable across a wide selection of simulation software and test equipment — from design verification through field diagnostics.

Boundary-scan test execution is controlled by the sequencing of TAP signals on the pins of the devices. Each device's behavior is determined solely by the states of its TAP pins. Boundary-scan tools must maintain knowledge of the sequences required to exert certain behaviors within a device and where that device is located in the serial scan path.

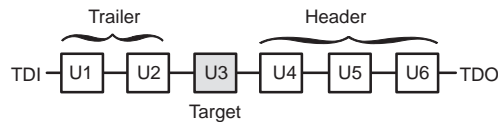
SVF controls the IEEE Std 1149.1 test bus using commands that transition the TAP from one steady state to another. Rather than describe the explicit state of the IEEE Std 1149.1 bus on every TCK cycle, SVF describes it in terms of transactions conducted between stable states. For instance, the process of scanning in an instruction is described merely in terms of the data involved and the desired stable state to enter after the scan has been completed. The Capture, Update, Pause, etc. states are inferred rather than explicitly represented. The data to be scanned in, expected data out, and compare mask are all grouped in an easily understandable manner. A command is provided to support deterministic navigation of TAP states where required.

In addition to supporting higher level depictions of scan operations, SVF also supports combined serial and parallel operations. This allows SVF to accommodate ATE environments where some stimulus/response is handled via parallel I/O, and serial signals are accessed via an IEEE Std 1149.1-control environment.

SVF also supports the concept of scan offsets. Offsets allow a test to be applied to a component or cluster of logic embedded in the middle of a scan path. In Figure 5-1, a device exists in multiple instances on a board. Serially applied tests were generated by the designer that are available in SVF format. To reuse this test, it is necessary to

put all other devices on the scan path into the *BYPASS* mode. The IEEE Std 1149.1 test controller must therefore comprehend 24 instruction register bits (8-bit IR x 3 devices) before and 16 instruction register bits (8-bit IR x 2 devices) after the target device. Once in *BYPASS*, the devices introduce three data register bits before and two data register bits after the target device.

SVF allows a header and trailer to be defined once, which maintains the instruction register and data registers of the nontargeted devices in the desired *BYPASS* state. No modifications are required to the SVF for the device. In Figure 5-1, if the same test were targeted toward another device downstream, this would be accommodated merely by changing the headers and trailers.



**Figure 5-1. Scan Path of Six ICs**

The offset approach is capable of installing any instruction register and data register stimulus, provided these values are constant for the entire process of applying the SVF device sequence.

**SVF Structure**

The SVF file is defined as an ASCII file that consists of a set of SVF statements. Statements are terminated by a semicolon (;) and may continue for more than one line. The maximum number of ASCII characters per line is 256. SVF is not case sensitive, and comments can be inserted into an SVF file after an exclamation point (!) or a pair of slashes (//).

Each statement consists of a command and parameters associated with that specific command. Commands can be grouped into three types: state commands, offset commands, and parallel commands.



### State Commands

State commands are used to specify how the test sequences will traverse the IEEE Std 1149.1 TAP state machine. The following state commands are supported:

<i>SDR</i>	Scan data register
<i>SIR</i>	Scan instruction register
<i>ENDDR</i>	Define end state of DR scan
<i>ENDIR</i>	Define end state of IR scan
<i>RUNTEST</i>	Enter Run-Test/Idle state
<i>STATE</i>	Go to specified stable state
<i>TRST</i>	Drive the TRST line to the designated level

*SDR* performs an IEEE Std 1149.1 data register scan. *SIR* performs an IEEE Std 1149.1 instruction register scan. *ENDDR* and *ENDIR* establish a default state for the bus following any data register scan or instruction register scan, respectively. *RUNTEST* goes to Run-Test/Idle state for a specific number of TCKs. For each of the above commands, a default path through the state machine is used. Each of these commands also terminates in a stable, nonscannable state.

*STATE* places the bus in a designated IEEE Std 1149.1 stable state. *TRST* activates or deactivates the optional test-reset signal of the IEEE Std 1149.1 bus.

### Offset Commands

Offset commands allow a series of SVF commands to be targeted toward a contiguous series of points in the scan path. Examples would be a sequence for executing self-test on a device, or a cluster test where all devices involved in the cluster test are grouped together. The following offset commands are supported:

<i>HDR</i>	Header data for data bits
<i>HIR</i>	Header data for instruction bits
<i>TDR</i>	Trailer data for data bits
<i>TIR</i>	Trailer data for instruction bits

*HDR* specifies a particular pattern of data bits to be padded onto the front of every data scan. *HIR* specifies the same for the front of every instruction register scan. *TDR* and *TIR* specify data to be injected on the back of each scan. These patterns need only be specified once and are included on each scan unless changed by a subsequent *HDR*, *HIR*, *TDR*, or *TIR* command.

#### *Parallel Commands*

Parallel commands are used to map and apply the following commands:

*PIO* — Specifies a parallel test pattern

*PIOMAP* — Designates the mapping of bits in the *PIO* command to logical pin names

Parallel commands allow SVF to combine serial and parallel sequences. *PIOMAP* commands are used by parallel I/O controllers to map data bits in the command into parallel I/O channels using the ASCII logical pin name as a reference. The *PIO* command specifies the execution of a parallel pattern application/sample. SVF does not specify any other properties of parallel I/O such as drive, levels, or skew.

#### **Default State Transitions**

SVF uses names for the TAP states that are similar to the IEEE Std 1149.1 TAP state names. Table 5-1 lists the SVF equivalent names for the TAP states.

**Table 5-1. SVF TAP State Names**

<b>IEEE Std 1149.1 TAP State Name</b>	<b>SVF TAP State Name</b>
Test-Logic-Reset	RESET
Run-Test/Idle	IDLE
Select-DR-Scan	DRSELECT
Capture-DR	DRCAPTURE
Shift-DR	DRSHIFT
Pause-DR	DRPAUSE
Exit1-DR	DREXIT1
Exit2-DR	DREXIT2
Update-DR	DRUPDATE
Select-IR-Scan	IRSELECT
Capture-IR	IRCAPTURE
Shift-IR	IRSHIFT
Pause-IR	IRPAUSE
Exit1-IR	IREXIT1
Exit2-IR	IREXIT2
Update-IR	IRUPDATE

Table 5-2 identifies sample default paths taken when transitioning from one state to a specified new state. For example, if the current state is RESET and DRPAUSE is selected as the end state, the TAP moves from RESET through IDLE, DRSELECT, DRCAPTURE, DREXIT1 to DRPAUSE. One must only specify the current and end states and not each intermediate step. See the TAP controller state diagram on page 3-5 of Chapter 3, *Boundary-Scan Architecture and IEEE Std 1149.1* to determine state transition paths not shown in Table 5-2.

**Table 5-2. Stable-State Path Examples**

Current State	End State	State Path
RESET	RESET	RESET
RESET	IDLE	RESET IDLE
RESET	DRPAUSE	RESET IDLE DRSELECT DRCAPTURE DREXIT1 DRPAUSE
RESET	IRPAUSE	RESET IDLE DRSELECT IRSELECT IRCAPTURE IREXIT1 IRPAUSE


### SVF Example

The following is an example SVF file:

```
! Begin Test Program
! Disable Test Reset line
  TRST OFF;
! Initialize UUT
  STATE RESET;
! End IR scans in DRPAUSE
  ENDIR DRPAUSE;
! End DR scans in DRPAUSE
  ENDDR DRPAUSE;
! 24 bit IR header
  HIR 24 TDI (FFFFFF);
! 3 bit DR header
  HDR 3 TDI (7);
! 16 bit IR trailer
  TIR 16 TDI (FFFF);
! 2 bit DR trailer
  TDR 2 TDI (3);
! 8 bit IR scan, load BIST opcode
  SIR 8 TDI (41) TDO (81) MASK (FF);
! 16 bit DR scan, load BIST seed
  SDR 16 TDI (ABCD);
! RUNBIST for 95 TCK Clocks
  RUNTEST 95 TCK ENDSTATE IRPAUSE;
! 16 bit DR scan, check BIST status
  SDR 16 TDI (0000) TDO(1234) MASK(FFFF);
! Enter Test-Logic-Reset
  STATE RESET;
! End Test Program
```

The test begins by deasserting TRST. The DRPAUSE state is established as the default end state for instruction register scans and data register scans. Twenty-four bits of header and 16 bits of trailer data are specified for instruction register scans. No status bits are checked. Three bits of header data and two bits of trailer data are specified for data register scans.

In the example above, a single device in the middle of the scan is targeted. Notice from the 24-bit IR header (3 x 8-bit IR) and the 3-bit DR header (3 x 1-bit DR) that the targeted device has three devices before it in the scan path. From the 16-bit IR trailer (2 x 8-bit IR) and the 2-bit DR trailer (2 x 2-bit DR), the targeted device has two devices following it in the scan path. After the header and trailer offsets are established, all subsequent scans are the concatenation of the header, scan data, and trailer bits. The targeted device supports BIST, which is initialized by scanning hex 41 into the instruction register, followed by hex ABCD into the



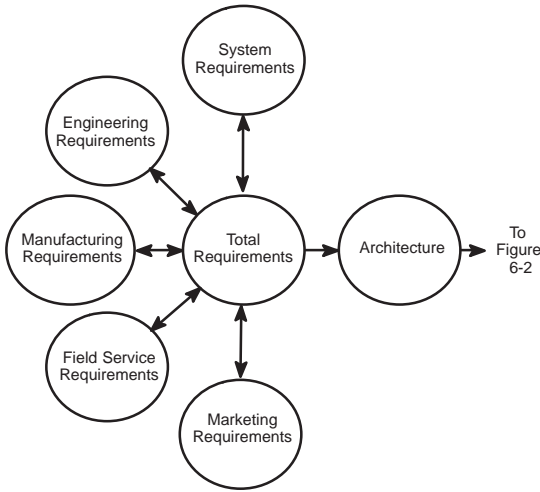
selected data register. The BIST in the targeted device is then executed by entering the Run-Test/Idle state for 95 clock cycles. Next, the BIST result is scanned out and the status bits compared against a deterministic value to determine pass/fail.

***How to Receive the SVF Specification***

Originally developed by Texas Instruments (with Teradyne) primarily in support of its ASSET business, SVF is now supported by ASSET InterTech, which acquired ASSET™ in 1995.

## Chapter 6 Suggested Design-for-Test Flow

The designer of any new product must plan for testing at any time in the life cycle of the product. This process is called design for test (DFT). The test methodology, defined by IEEE Std 1149.1, is used to ease problems associated with both product development and all levels of testing. Once boundary-scan architecture is built into a device, tests developed for that device can be reused after it is in a product. Figure 6-1 summarizes the concerns applicable to any new product design.



**Figure 6-1. Initial DFT Concerns**

## Test Requirements

Before implementing a boundary-scan test scheme, the designer must define test requirements for the following phases of the product life cycle:

- Design verification
- Manufacturing test
- Field test (also can be used for incoming inspection)

These studies must ensure that the necessary controls are designed into the hardware to support the following requirements:

- During design verification, an engineer requires controllability of the circuitry, both internal to the IC and at board and system levels. Design engineers need controllability and observability of every logic node in the system. If this proves to be unrealistic, reasonable coverage is achievable with partial scan in a boundary-scan design.
- Manufacturing test may include interconnect testing and functional logic validation.
- Field or embedded testing typically may only include the ability to report faults and to isolate a fault to a field-repairable unit (board or subsystem).

For both manufacturing test and field test, IEEE Std 1149.1 logic and test vectors can be used to test clusters or blocks of logic.

Internal IC testing at the board or system level requires a subset of the complete IC logic-verification patterns to validate basic IC logic functions. Each level of hierarchical testing has a different set of fault characteristics. IEEE Std 1149.1 logic can be used throughout the testing life cycle of the product.





### **Built-In Self-Test (BIST) Methodology**

BIST usually consists of special circuitry built as part of an IC's internal design. BIST tests typically perform these functions:

- Pseudorandom pattern generation (PRPG)
- Parallel signature analysis (PSA)
- Serial signature analysis (SSA)
- State machine-based generation/comparison

IEEE Std 1149.1 commands can initiate BIST tests and return the test results.

### **Internal Scan Test Methodology**

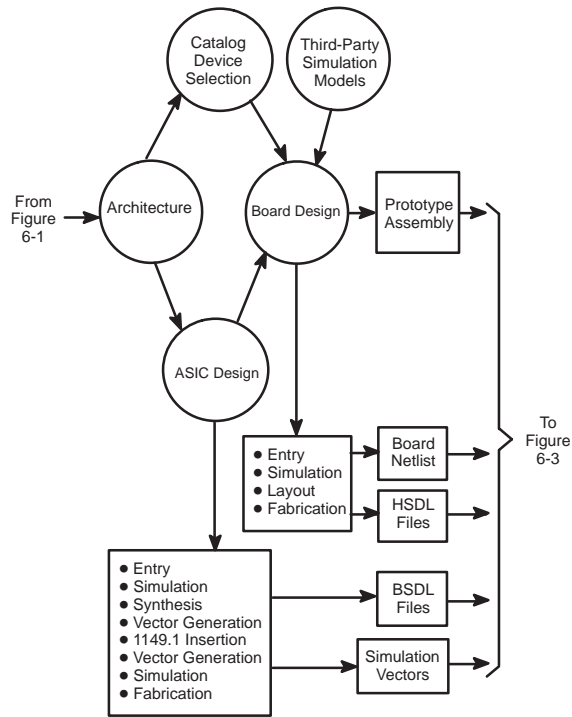
Many high-density microprocessors and ASICs now include internal IEEE Std 1149.1-compliant scan circuitry. High-pin-count and fine-pitch packages limit physical access to package pins and devices with high gate count limit observation of the internal logic states. Internal scan, either partial or full, can do the following:

- Provide access to internal registers
- Partition the design
- Reduce the design to combinatorial networks surrounded by scannable registers
- Provide fast, efficient testing of internal logic

Internal scan also allows on-chip emulation control and circuit observability within a device to provide design verification. The emulation capability also can aid in software development to control highly complex functions designed into a device.

### Design Effort

Figure 6-2 summarizes the various steps involved in ASIC and board design.



**Figure 6-2. Designing Testability for ASICs and Boards**

### IC Design Implementation

Synthesis of ASICs has become a popular approach to ASIC design. ASIC designers faced with DFT for the first time are concerned about lack of knowledge and the additional design time involved. Today, there are several vendors supporting synthesis and/or insertion tools that can automatically

generate the following elements of an IEEE Std 1149.1 architecture:

- Test access port (TAP) controller
- Instruction register
- Instruction decode logic
- Bypass register
- Boundary-scan register

Such tools also can automatically generate test vectors for IEEE Std 1149.1-compliant designs. This means that a designer can quickly and correctly implement basic IEEE Std 1149.1 test circuitry in an ASIC.

If synthesis is not available, most ASIC vendors offer a library of macros that the designer can use to implement IEEE Std 1149.1 into their designs. Using vendor macros requires considerably more effort and knowledge to implement IEEE Std 1149.1 into an ASIC, compared to using synthesis. However, in the absence of synthesis or boundary-scan insertion tools, using vendor macros is significantly easier than implementing boundary-scan architecture using a library that has no such macros. Texas Instruments offers a family of IEEE Std 1149.1-compliant ASIC macros for gate array and standard cell designs.

The ASIC designer is required to provide a Boundary-Scan Description Language (BSDL) file that describes the finished ASIC. This information becomes the basis for tools that automatically create board interconnect test vectors. These vectors can be used by the board designer for debug and validation and by manufacturing test departments for quality assurance.

Several DFT tool vendors plan to implement automatic BSDL creation that is available once the ASIC design has been completed. The creation of a BSDL file by the ASIC designer is straightforward if the design tool used does not automatically create it.

### **IC Simulation**

During IC simulation, the designer can use IEEE Std 1149.1 logic to simplify the simulation patterns required to validate the design. First, patterns must be developed to verify that the IEEE Std 1149.1 interface is operating properly. Simple IR and DR scan patterns can be developed to perform this check. If internal scan is implemented, then simulation pattern sets can be written to test internal logic clusters using the internal scan registers. This partitioned approach simplifies design validation.

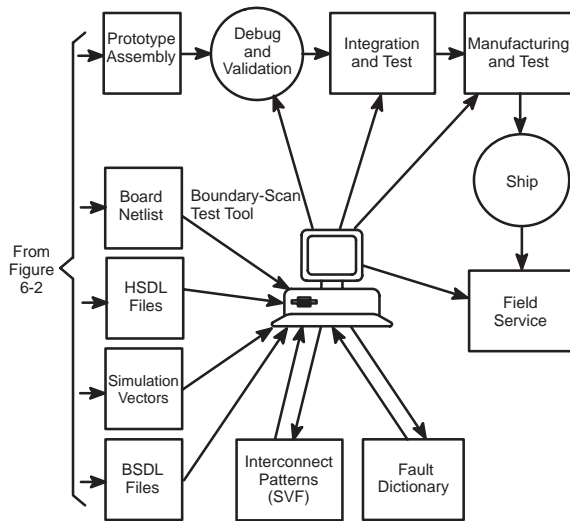
### **Using SVF for IC Design Validation**

Many IEEE Std 1149.1-compliant tools use Serial Vector Format (SVF) as the primary test pattern data format and interfaces between simulators and ATE testers also support SVF.

A collection of manually-generated SVF patterns, simulation patterns translated into SVF and ATPG-generated SVF patterns can be used to validate the IEEE Std 1149.1 logic. Initial tests must first verify that serial data can be scanned into and out of the IC. Proper use of internal scan registers to partition the internal functional logic can simplify fault detection and isolation.

IC testing usually is broken into three parts; static functional tests at 1 MHz, at-speed functional tests, and parametric tests. Because IEEE Std 1149.1 architecture relies on serially scanning control and test data, only static functional testing and DC parametric testing can be performed via the IEEE Std 1149.1 architecture. However, the IEEE Std 1149.1 TAP can be used to access user-defined test instructions (such as *RUNBIST*), which can be operated at speed.

*INTEST* patterns generated by a simulator can be used to validate the internal logic of the IC. By comparing these patterns with simulation results and by observing internal scan register contents, the designer can isolate faulty internal logic. Figure 6-3 summarizes the design validation flow for all products, from IC through system-level products.



**Figure 6-3. Debug and Verification of a Boundary-Scan Design**

**Data Passed to Board Designer**

The board designer needs test data to use during the design debug and validation phase. This data includes:

- BSDL for the ASICs as developed by the ASIC designer
- BSDL for catalog devices from the device vendor

The BSDL that the designer creates for the ASIC must be validated to ensure that it is correct since it will be used by tools that develop more tests for board debug and validation. The new tests are then applicable for manufacturing test and field service test vector generation. BSDL created by a synthesis tool should accurately reflect a device's construction.

Along with the BSDL file for the device, the ASIC designer may also be asked to provide a subset of the ASIC simulation patterns if the ASIC supports the optional *INTEST* instruction. A subset of the simulation patterns may consist

of the static (1-MHz) functional patterns. Only a subset of patterns may be needed because it may be impractical to reapply the entire static functional test pattern set at the board level. Many companies have found that they can achieve an acceptable level of confidence that the ASIC is functioning correctly using only a portion of the entire static functional pattern set.

### **Board Design**

Most of the concepts described for IC design also apply to board and system integration. BSDL is used to describe the IEEE Std 1149.1 scan architecture of an IC, and Hierarchical System Description Language (HSDL) is used to describe subsystems and systems. HSDL is used to describe the scan architecture, group discrete signals into logical groups (e.g., ADDR0–15, DATA0–7) and to define constraints.

### **Constraints**

A constraint defines a logic condition that can apply potentially harmful signals to a circuit. IEEE Std 1149.1 gives direct control of all scannable signals, so it is possible to create logic states that functionally would not be entered. For example, bus-arbitration logic can be overridden and dangerous hardware conditions or conflict can occur. An example of a constraint is to inhibit any test pattern that would cause two scannable output nodes to drive a common bus net at the same time.

### **Partitioned Scan Path**

At the board level, the designer must consider how to partition the IEEE Std 1149.1 scan path. Commercial devices are available (such as TI's SN74ACT8997† SPL) to switch a single primary scan path to one or more multiple secondary scan paths. The designer should consider the benefits and penalties associated with partitioned scan paths.

† SN54ACT8997, SN74ACT8997 Scan Path Linkers With 4-Bit Identification Buses, Literature Number SCAS157C, Texas Instruments 1996.

Penalties associated with partitioned scan paths include:

- Scan overhead required to switch from one partition to another
- Timing delays in routing TMS (affecting scan frequency)
- Added complexity of the IEEE Std 1149.1 test program

Benefits associated with partitioned scan paths include:

- Shorter scan paths
- Additional fault tolerance
- Somewhat simplified test software

### **Board Validation/Manufacturing Test**

The IEEE Std 1149.1 architecture has the ability to detect, and in many cases, isolate a scan path fault. The instruction register definition requires that the two (2) least-significant bits (those closest to TDO) of a device be, respectively, a logic 1, followed by a logic 0 during an IR scan. This rule allows the IEEE Std 1149.1-compliant bus controller to perform a simple IR scan to prove all devices on the bus can drive a logic 1 and logic 0 on the TDI–TDO path. There are ATPG tools available that automatically generate SVF bus validation patterns that can be applied by the bus controller.

The primary objective of IEEE Std 1149.1 is to allow control and observation of device input and output pins for the purpose of interconnect testing. The reduced size of IC packages has made interconnect testing of PWBs difficult and expensive when using conventional interconnect testing. Commercial tools are available that automatically generate SVF patterns for interconnect testing. Such tools input a board netlist and the BSDL of the scannable components and output an SVF pattern set. This pattern set, along with a fault dictionary lookup table, allows an IEEE Std 1149.1 bus controller to apply the interconnect patterns to the board and detect/isolate faulty interconnections.

After proving correct operation of the IEEE Std 1149.1 bus and board interconnect, the designer can control and observe all boundary-scan nodes. Commercially available boundary-scan test tools allow interactive, macro, or high-level-language programming control for the designer. The board designer also can import and reapply the SVF patterns developed by the IC designer. This reuse of pattern sets provides these benefits:

- Knowledge is passed from one designer to another.
- Overall product development cycle is reduced.
- Using common SVF patterns reduces ambiguity between hierarchical test levels.

The SVF pattern set developed by the IC designer tests an individual IC. The board designer has to be able to relocate the relative scan position of the IC SVF test to match its scan position on the board dynamically. SVF headers and trailers can be manipulated by the boundary-scan test tool to allow such dynamic test relocation.

### Summary

As designers become better acquainted with IEEE Std 1149.1, they will no doubt find benefits well beyond those discussed in this chapter. The standard became available just in time to offer solutions and benefits to customers experiencing complex problems introduced by new technology.

The benefits that customers can realize from IEEE Std 1149.1 architecture include:

- Reuse test data throughout the product life cycle
- Apply off-the-shelf components, tools, and ATE solutions from multiple vendors
- Maintain common data base formats for these benefits:
  - Shared common databases between IC, board, and system designers (BSD, HSDL)
  - Reusable pattern sets (SVF)
  - Reusable test pattern set (TPS) code



## Chapter 7 Applications

This chapter presents a number of testing problems and shows how boundary-scan testing and TI products can be used to solve them.

### Board-Etch and Solder-Joint Testing

The current approach to detecting board-etch and solder-joint faults in today's electronics industry uses two forms of automatic test equipment (ATE): bare-board testers and digital in-circuit testers. Bare-board test is done after board fabrication. Tests for open-etch circuits between nodes force a voltage onto one circuit node and sense the voltage at another circuit node. This technique is used only on a raw, unassembled board.

An in-circuit test is done after board assembly and checks for:

- Correct orientation of parts
- Correct value and type of parts
- Correct solder joints between all parts and the board

Software models of each part on a board are used to generate the test patterns used by the in-circuit tester. The main assumption is that both board and in-circuit testers require physical access to nodes or points on the board to perform the necessary testing. Both testers require the ability to inject a voltage or current onto a nodal network and sense the voltage or current at another point on the network.

Higher-density packaging technologies, finer-pitch board etch, and more complex digital integrated circuits have made bare-board and in-circuit testing much more expensive.

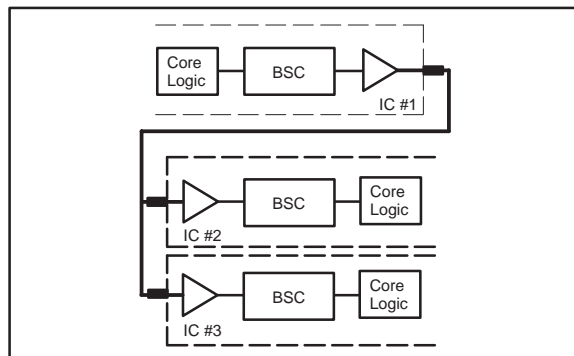
### ***Solution***

Several testability products from Texas Instruments lend themselves to support IC-to-IC continuity testing. The techniques outlined allow detection and, in most cases, isolation of board-etch and solder-joint faults, without forcing any additional requirements on the electrical design engineer. ASIC devices and bus-interface components with

boundary-scan cells (BSCs) allow controlled insertion of digital logic values onto a nodal network and provide the means to sample the digital logic values on the nodal network. Broken-etch and solder-joint faults can be detected and isolated in this manner.

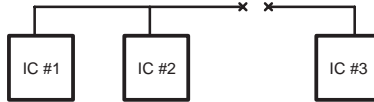
**Detailed Description**

In the simple circuit shown in Figure 7-1, one driver (IC #1) on a network drives digital logic values while the other receivers (ICs #2 and 3) sense changing values on the net. If multiple driver ICs exist on a network, each driver is allowed to drive, in turn, while all receivers sense to detect and isolate a fault to a specific driver or portion of the net.

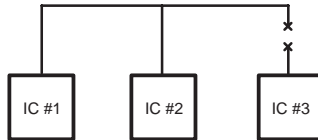


**Figure 7-1. Etch/Interconnect Testing**

If an etch is broken on a network or an IC is not soldered to the board properly, then nodes of some ICs are not connected to nodes on others, as shown in Figure 7-2 and Figure 7-3 . When driver IC #1 drives, only IC #2 senses the correct logic value; IC #3 does not.

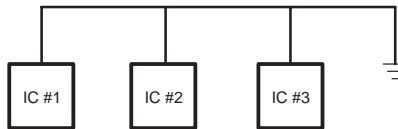


**Figure 7-2. Open-Etch Condition**



**Figure 7-3. Open-Solder-Joint Condition**

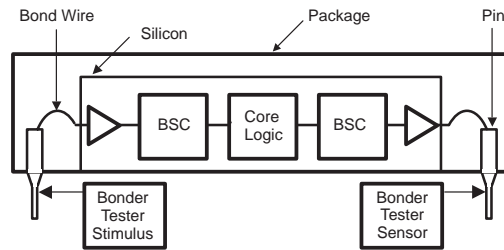
If an etch is shorted to ground or power due to a solder fault, then none of the ICs are able to drive or sense the correct logic values. See Figure 7-4.



**Figure 7-4. Short-to-Ground Condition**

The overall coverage of etch- and solder-fault detection and isolation depends on the percentage of a board's circuitry that has boundary-scan architecture. Only networks driven by BSCs or IEEE Std 1149.1-compliant ICs can be tested in this way; nonscan-controlled networks require conventional approaches.

Because the driver and receiver BSCs are in silicon within the ASIC, this technique can be used to test silicon bonding to package pins in the integrated-circuit foundry. A simple bond-out tester can drive a logic value to an input pin of an IC and the sensing function can occur on the BSC buffering the input to the core logic of the ASIC. The reverse procedure can be used on an output pin of an IC; the BSC driving the output of the core logic forces a logic value that the bond-out tester senses and records. See Figure 7-5.



**Figure 7-5. Bond-Wire Testing**

**Summary**

The current technique used to detect and isolate board-etch and solder-joint faults remains unaltered. With TI's suite of testability products, board testing can be performed without external digital in-circuit testers. Boundary-scan architecture eliminates the need for physical probe points on printed-circuit boards that contain advanced-packaged, surface-mount integrated circuits. The need to develop part models for in-circuit test generation also is eliminated.

### Cluster Testing

Complex digital designs use large-scale integrated circuits and ASICs to accomplish many functions on compact circuit boards. Not all logic functions are integrated, so discrete devices are still used for some functions. Discrete logic seldom includes boundary-scan test architecture due to the expense and complexity; these parts must be tested another way.

### Solution

Testing discrete logic functions on a board has to be done from the boundary of the logic cluster. Combinatorial logic is normally driven by and into sequential elements such as a register or a clocked ASIC. By replacing the register with a IEEE Std 1149.1-compliant device, or by using Texas Instruments IEEE Std 1149.1-compliant macro cells at the boundary of the ASIC, the cluster logic may be easily tested. By using members of TI's family of testability products, a higher percentage of circuitry may be tested while reducing the vector count necessary to perform a functional test.

### Detailed Description

Figure 7-6 shows a simple circuit incorporating combinational logic sandwiched between sequential logic.

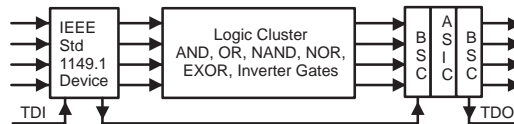


Figure 7-6. Cluster Testing

During normal circuit operation, the IEEE Std 1149.1-compliant device drives the glue logic through to the BSCs in the ASIC. Two methods may be used to perform a test of the logic cluster using the TI family of testability products. There are benefits and drawbacks to both methods.

1. Method one is to scan a fixed-order set of test patterns called *deterministic test vectors* into the IEEE Std 1149.1-compliant device and sample the resultant data at the ASIC boundary.
2. Method two is to command the IEEE Std 1149.1-compliant device to output a pseudorandom pattern of data while the ASIC performs a parallel signature analysis of its inputs.

#### *Deterministic Test Vectors*

Deterministic test vectors scanned into the UUT can pinpoint a problem more easily than signature analysis. Since the exact input stimulus is known, the failing response can be detected. Deterministic test vectors perform a complete and meaningful test, but consume a lot of time and enough memory to store all vector data for both stimulus and response.


#### *Signature Analysis*

Signature analysis can be performed quickly and virtually automatically. After valid pattern generation and signature analysis seed values are obtained, the resultant signature can be checked against the correct value. This test can be performed at the scan clock speed and requires very little memory for data storage. However, the fault cannot be located without using an extensive fault dictionary.

Signature analysis requires that the IEEE Std 1149.1-compliant device be able to generate stimulus patterns and the ASIC be able to capture a signature of its inputs. This means that appropriate macro cells must be used as outputs of the driving device and as inputs to the boundary of the ASIC. These cells require additional space and additional circuitry to be incorporated into each BSC.

#### **Summary**

Using the IEEE Std 1149.1-compliant family of testability products from Texas Instruments enables designers to add



features previously unachievable in their designs. It is beneficial to test glue-logic clusters using existing boundary-scan components that surround the logic cluster. This provides added value to the boundary-scan overhead built into a design's larger devices.

### **Board-Edge Connector Testing**

Board-to-board fault detection and isolation within a digital system have historically depended primarily on built-in test (BIT) software. This approach is adequate for detecting functional faults on boards, assuming that the processor executing BIT software can access the boards installed in the system. Backplane faults typically manifest themselves in these ways:

- Broken or bent pins on connectors
- Broken etch on a backplane motherboard
- Termination-network fault
- Bus contention on a bused network

Many bus faults in today's digital processor environments are so catastrophic in nature that the processor executing BIT cannot access the boards installed within the system to isolate the fault.

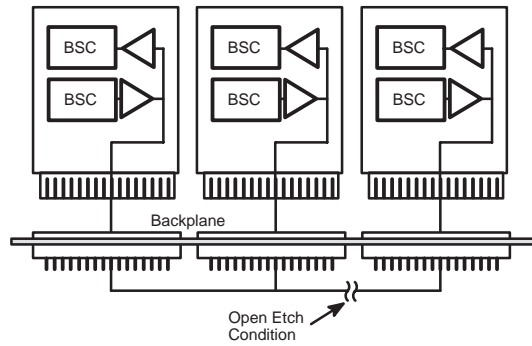
#### ***Solution***

In much the same way that boundary scan allows detection and isolation of etch and solder-joint faults on a PWB, surrounding the bus interface of a board with IEEE Std 1149.1-compliant devices allows detection and isolation of bus and connector faults. By placing IEEE Std 1149.1-compliant devices in a controlled test mode, each board, in turn, can drive the backplane bus while the other boards receive the driven logic values.

#### ***Detailed Description***

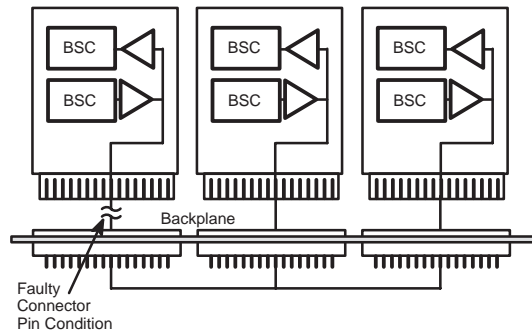
Broken etch on a motherboard backplane presents problems similar to that of broken etch on a PWB connecting integrated circuits; some boards cannot communicate to others past the etch break (see Figure 7-7). By placing the testability devices on each board into a controlled test mode,

one board at a time can drive logic data onto the bus while the others are receiving logic data. This method provides enough conclusive data to detect and isolate the continuity break.



**Figure 7-7. Backplane Open-Circuit Fault**

A broken connector pin fault can be detected and isolated in the same manner as etch breaks; the board with a bad pin is not able to drive and receive data onto a particular channel on the backplane. See Figure 7-8.

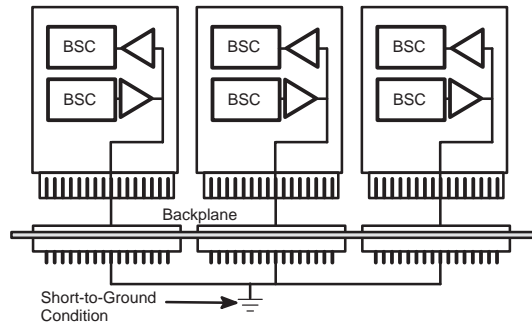


**Figure 7-8. PWB Connector Fault**

Termination network open or short to  $V_{CC}$ /ground shows up as a channel on the backplane that cannot be driven to a



certain logic state. The characteristic of this fault could be confused with a bus contention fault. See Figure 7-9.



**Figure 7-9. Backplane Short-to-Ground Fault**

Bus contention faults occur when a three-state bus driver is stuck in a functional-enable mode. The BSCs in a controlled mode can be disabled by the test circuitry, thus bypassing the functional-enable control. All of the tests described can be executed offline in a test mode or by built-in test (BIT) software interfacing to an IEEE Std 1149.1-compliant serial scan controller in the system.

#### **Summary**

Board-to-board fault detection and isolation in a controlled offline test mode and concurrent background BIT execution can be dramatically improved by using boundary-scan testability devices within the bus interface circuitry of each board installed in a system. Boundary-scan architecture at the backplane-interface can increase fault isolation by masking some interface logic from the circuitry under test.

## **ASIC Verification**

Very-high-density ASIC devices pose severe barriers to all testing, beginning with design verification and continuing with test and verification of the manufactured part.

### ***Solution***

IEEE Std 1149.1-based testing can be used for testing and verifying ASIC devices if the design process, beginning with design specifications, includes scan-based testing. This example cites the development of a *vector processor* ASIC with 165,000 gates.

### ***Detailed Description***

The test logic in the vector processor includes internal scan and built-in emulation logic, in addition to boundary scan and the optional *INTEST* capability. The emulation capability includes control of the processor, implementing RUN, STOP, SINGLE-STEP, and EXAMINE/MODIFY internal registers, and real-time breakpoints.

### ***Test Development***

Design verification, test hardware, and test software are developed concurrently with the ASIC. Verification code consists of two types of tests:

- Scan-based tests and diagnostics
- Embedded test code

A boundary-scan test tool is used to execute and monitor boundary-scan tests. The tests are used to verify test bus operation, scan path integrity, internal-register access, core-logic operation, and IC-to-IC interconnects. An expanding set of scan-based utilities and special-purpose test programs are written to perform specific tests or troubleshoot hardware problems. These utilities are developed from the time hardware integration is begun.

In addition to the scan-based tests, embedded test code is developed in microcode to verify instruction set execution, register and memory decode, memory access, and input/output operations. The embedded tests target functional logic and verify at-speed operations.



### *Design Verification*

The vector processor ASIC in the design incorporates extensive internal scan paths and breakpoint logic controlled via the IEEE Std 1149.1 test bus. Key registers that are accessible via scan include the address and data register files, ALU and multiplier pipeline registers, and the program instruction register.

Initial checkout of the vector processor includes scan path integrity and internal register access using internal scan and boundary scan. The first devices contain nonfunctional microcode RAM, therefore an alternate plan is devised to use IEEE Std 1149.1 to validate all other circuitry.

The vector processor checkout uses the boundary-scan architecture to perform register reads and writes and simple operations to verify microcode execution. Simple microcode operations are tested by scanning an opcode into the instruction register and clocking the processor using boundary scan.

A test routine is developed in C++ that automates the microcode execution steps. The program reads microcode-object files, scans the instruction into the instruction register, clocks the processor, and reads the program counter to locate the next instruction. As each instruction is executed, the program dumps the accumulator and status registers to allow monitoring of each instruction. This process is repeated for each microcode routine until all microcode is executed and nearly all processor functions are verified using the "bad" vector processors. Many weeks are saved while waiting for new vector processors.

### **Summary**

Design verification, hardware test, and software integration represent significant challenges. Anticipating this, many design-for-test and integration capabilities need to be incorporated into the device to ensure controllability and observability of embedded functions. IEEE Std 1149.1 provides the primary method for design verification, hardware/software integration, and hardware test.

Test and interaction issues in this case were aggravated by the lack of physical access caused by the small geometry of the module. Boundary-scan testing saved a significant

portion of the design verification effort that would have been required for the less-effective conventional physical access methods.

### **Memory-Testing Techniques**

The steady increase in memory density has led to the increased use of high-capacity memory boards in today's electronic systems. It has also encouraged the use of embedded memory within microprocessors, digital signal processors (DSP), and ASICs. As a result, testing of these boards and devices has become more complex. Large-capacity memory boards require very long test execution times for adequate fault detection. Large bus sizes (32 bits) and high bus fanout further complicate the problem of isolating component faults. Embedded memories, which often make up a significant portion of the device area, create additional difficulties due to a lack of test access.

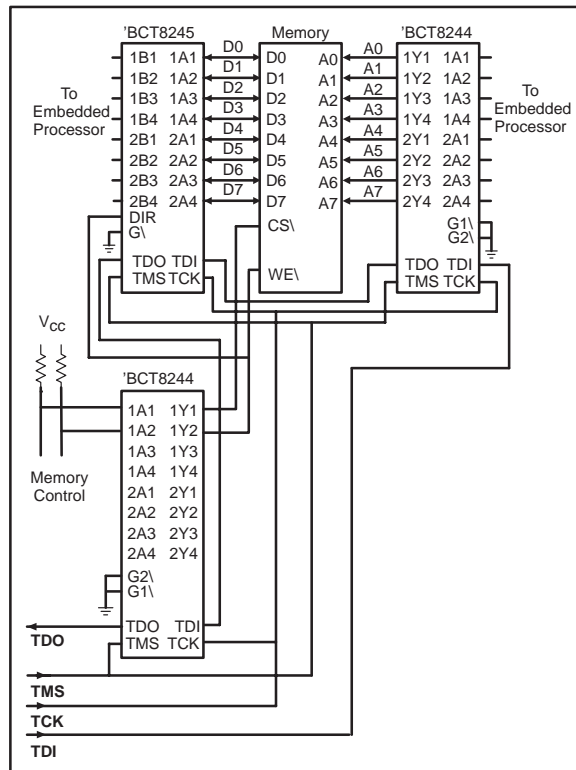
### **Solution**

The use of scan-path technologies can simplify the problem of testing large memory arrays within a system or embedded memories within a device. Scan-path devices such as TI's bus-interface components can be used to partition large memory device arrays into smaller, more easily testable arrays to increase component fault isolation. In addition, the use of TI's IEEE Std 1149.1-compliant macro cells within ASIC devices provides controllability and observability of embedded memory that is normally inaccessible. Memory test times can be reduced through the efficient partitioning and testing of several memory arrays (on a board or within a device) in parallel.

### **Detailed Description**

Figure 7-10 shows a  $256 \times 8$  memory array, associated bus interface, and control logic configured to test various memory-pattern-generation techniques. This configuration allows for explicit read/write operations using IEEE Std 1149.1 *EXTEST* and *SAMPLE* instructions. In addition, the components have a BIST capability (controlled by IEEE Std 1149.1 instructions) used to perform memory read/write operations. The test results shown in Table 7-1 compare explicit scanning in the RAM array address, data, and strobe

signal to using an IEEE Std 1149.1-instruction-controlled BIST to generate address, data, and strobe signals automatically at the test clock (TCK) rate of 6.25 MHz.



**Figure 7-10. Block Diagram of Simplified Boundary-Scannable RAM Interface**

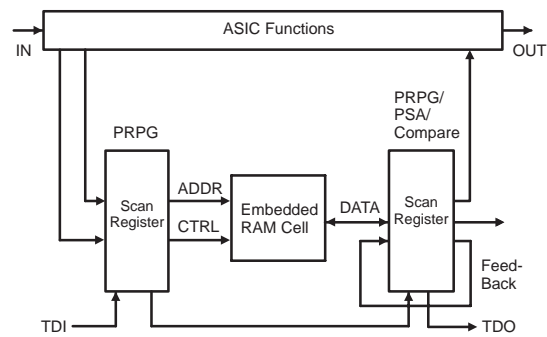
**Table 7-1. Access Rates of IEEE Std 1149.1 Devices With and Without BIST**

Mode	256 Accesses	1,000,000 Accesses
IEEE Std 1149.1 (With BIST Capabilities)		
Time to Apply	0.00041 seconds	<0.01 minutes
Number of Scans	7	28,000
Number of Patterns	512	2,000,000
IEEE Std 1149.1 (Using <i>EXTEST</i> and <i>SAMPLE</i> )		
Time to Apply	5.625 seconds	375.00 minutes
Number of Scans	512	2,000,000
Number of Patterns	512	2,000,000

Table 7-1 shows that the BIST controlled by IEEE Std 1149.1 instructions overcomes the limitations of conventional memory testing. Using boundary-scan *EXTEST* and *SAMPLE/PRELOAD* solves the direct physical access problem, but it is time consuming. By using BIST circuitry embedded within the functional logic surrounding large memory arrays, IEEE Std 1149.1 tests can be designed to emulate closely the characteristics and timing speeds of the memory being accessed. TI's bus-interface components offer the IEEE Std 1149.1-controlled BIST functionality required to test memory, while providing the electrical signal conditioning and buffering a design engineer typically designs around a microprocessor.

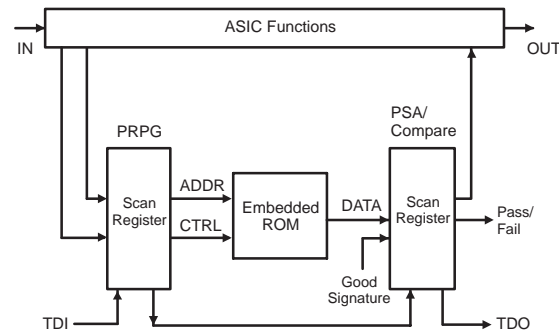
In a similar fashion, TI's family of IEEE Std 1149.1-compatible cells can be used within an ASIC device to provide access to embedded memory normally inaccessible through external pins. The IEEE Std 1149.1-compatible cells support the same self-test features as the bus-interface devices (PRPG, PSA, Toggle 1/0 modes), which further simplify memory testing. Additional features such as programmable PRPG and PSA taps, built-in comparison logic, maskable PSA/comparison inputs, and bidirectional cells provide even more flexibility in self-test design. These features can be used with a built-in test controller to create an autonomous BIST for the memory array and/or other functions within the device.

The use of IEEE Std 1149.1 cells in performing read/write tests on RAM is shown in Figure 7-11. Address sequencing is performed using the PRPG mode. The PRPG and toggle modes automatically generate data patterns to be written to the memory cells under test while the memory write enable is controlled by direct scan. When reading from memory, data patterns are verified using the comparison logic in the IEEE Std 1149.1-compatible cells. This is possible since each IEEE Std 1149.1-compatible cell can latch and remember the last data pattern that was written when configured correctly. During memory reads, the latched pattern is fed back for comparison with the data being read. A pass/fail signal for the test can be generated by combining the comparison outputs of each IEEE Std 1149.1-compatible cell.



**Figure 7-11. Testing Embedded RAM**

A similar testing method can be used when testing read-only memory (ROM) embedded within a device, as shown in Figure 7-12. During ROM tests, address sequencing and read enables are controlled as in Figure 7-11, and the PSA mode is used to compress the data output into a representative signature. If desired, comparison logic can be used to compare the calculated signature with a known good signature to generate a memory pass/fail signal.



**Figure 7-12. Testing Embedded ROM**

**Summary**

The use of TI's bus-interface components and boundary-scan cells provides increased fault detection and isolation capabilities when used to partition large-capacity memory boards and devices with embedded memory. The increased partitioning allows the use of parallel testing and autonomous built-in self test, greatly reducing the overall test execution times normally attributed to memory testing. IEEE Std 1149.1 bus-interface components provide simple replacements for buffers and transceivers that are normally used in memory system design, while creating little impact on system performance. TI's boundary-cell library is a completely configurable set of test cells that allows the designer to create sophisticated test structures (such as built-in self test for memories), while requiring only a minimal knowledge of test engineering principles.

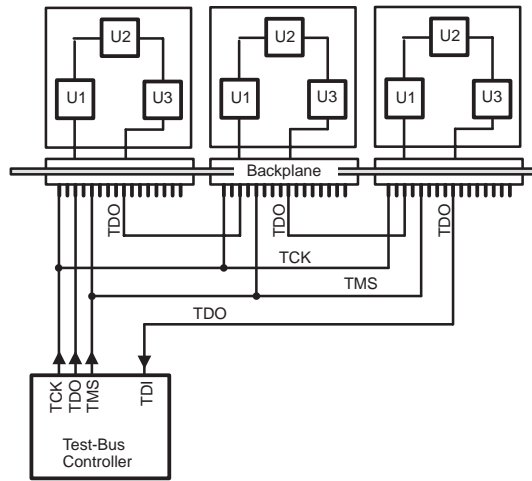


### **Backplane Multidrop Environment**

The backplane environment, which carries many signals in parallel to all the boards, contains certain conditions not found in other test situations. A typical backplane with a complement of boards (such as a computer that uses different accessory boards) may be configured differently for different purposes. In other cases, certain boards may be capable of interacting independently of normal backplane activity, and some boards may include BIST. For maximum usefulness and short test times, a test program must accommodate a partially populated backplane, while allowing more than one board to be active at a time.

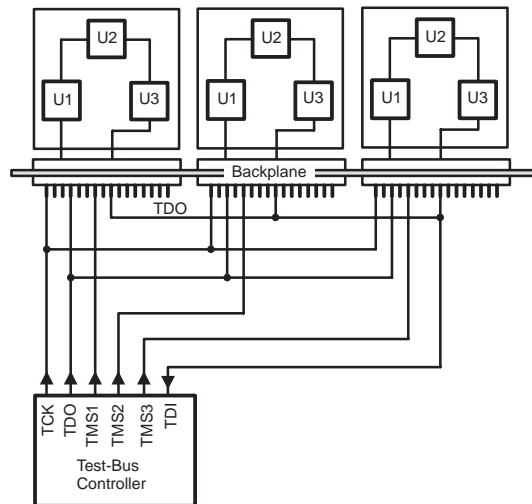
IEEE Std 1149.1 was developed to serially access ICs on a board, but it also can be used to access boards installed in a backplane. By making simple hardware modifications to the backplane circuitry, ring or star backplane configurations can be accessed using normal IEEE Std 1149.1 commands.

In a backplane configured as a ring (see Figure 7-13), all boards directly receive the TCK and TMS control outputs from a primary test-bus controller (TBC). The scan path is daisy chained between the TBC's TDO output and TDI input. During a test, the TBC drives TMS and TCK to scan data through all boards in the backplane, through the TDO/TDI bus connections. A serial path works only if all the boards are present and can scan data from their TDI input to TDO output. A missing or faulty board breaks the path, so the TBC cannot scan data through the backplane.



**Figure 7-13. Backplane Ring Configuration**

In a backplane star configuration (see Figure 7-14), the TBC drives TCK and TDI directly to all boards and each board outputs a TDO signal to the TBC. Each board requires a unique TMS signal from the TBC and a separate circuit trace for each signal. During testing, only one board is enabled at a time and only the TMS signal for that board is active. In a backplane with 50 boards, the TBC needs 50 individual TMS signals, with circuit traces for each. Another drawback is that only one board can be scanned at a time.



**Figure 7-14. Backplane Star Configuration**

**Solution**

A new serial bus protocol has been developed by Texas Instruments that is interpreted by a TI device called the Addressable Scan Port (ASP) (SN74ABT8996†). This device provides linkage between IEEE Std 1149.1-compatible boards and a backplane. The ASP becomes the IEEE Std 1149.1 input bus for each board in the backplane. It intercepts the protocol on the normal incoming IEEE Std 1149.1 signal wires, allowing it to connect or disconnect its board with the IEEE Std 1149.1 bus on the backplane. Once connected, the board can communicate using the IEEE Std 1149.1 protocol.

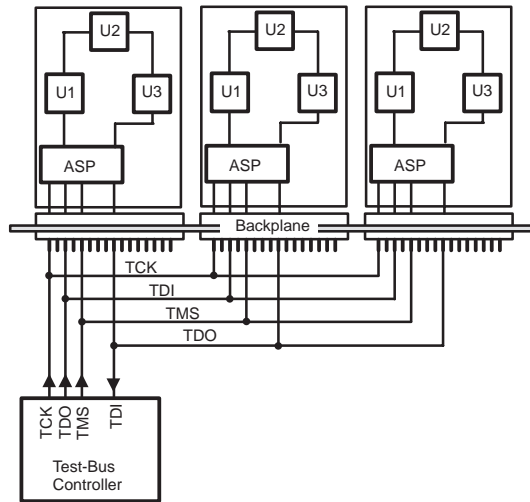
The ASP protocol is invoked when the IEEE Std 1149.1 bus is in one of the following four TAP states: Test-Logic-Reset, Run-Test/Idle, Pause-IR, or Pause-DR.

† SN54ABT8996, SN54ABT8996 10-Bit Addressable Scan Ports Multidrop Addressable IEEE 1149.1 (JTAG) TAP Transceivers, Literature Number SCBS489A, Texas Instruments 1996.

The protocol can address and select any ASP-equipped board in the backplane. After the board is connected to the IEEE Std 1149.1 bus, the ASP simply passes data through to the bus so normal operation can resume.

**Detailed Description**

Figure 7-15 shows a backplane with ASP devices on each board, allowing individual boards to be configured and active simultaneously.



**Figure 7-15. Backplane With ASP-Equipped Boards**

For example, if the interconnects between two boards are to be tested, it is necessary to select and scan the first board to output a test pattern, then select the other board to receive the test pattern. The ASP makes it possible to select and scan the second board without resetting the first board. During operation, each pattern of the interconnect test is scanned out of the receiving board before a new pattern is scanned into the driving board.

Another test may be to select and initiate self-tests in a selected group of backplane boards. The ASP allows BIST to start on each board and run while other board tests are initialized. Each board is then polled to read the test results, one board at a time.

### **Summary**

The special problems associated with backplane testing can be accommodated when the SN74ABT8996 Addressable Scan Port is added to individual boards.

### **Embedded Applications**

Field testing can be simplified if equipment is configured to take advantage of embedded IEEE Std 1149.1 functions.

### **Solution**

TI's SN74ACT8990† Test-Bus Controller (TBC) and SN74LVT8980‡ Embedded Test-Bus Controller (eTBC) devices can be embedded in system circuitry to provide autonomous IEEE Std 1149.1-based testing. A licensable, embeddable "C" source code product called Scan Engine, which includes test vector translators, is available to simplify embedded boundary-scan test applications.

### **Detailed Description**

TI's test-bus controller devices operate under the control of a host processor to master one or more IEEE Std 1149.1 scan paths. Appearing to the host as memory- or I/O-mapped peripherals, they accept parallel command and test data and convert it to appropriate IEEE Std 1149.1 protocols, as required. Thus, they allow the host software to operate at a high-level (essentially, at the level of SVF) rather than requiring that it encode knowledge of TMS state, sequencing, etc.

† SN54ACT8990, SN74ACT8990 Test-Bus Controllers, Literature Number SCAS190C, Texas Instruments 1996.

‡ SN54LVT8980, SN74LVT8980 Embedded Test-Bus Controllers, Literature Number SCBS676, Texas Instruments 1996.

#### *Host Interface*

Both TBC and eTBC devices implement a generic host interface. Each contains a set of memory- or I/O-mappable registers that can be read/written by the host to control its operation and monitor its status.

The host interface of the TBC consists of a 16-bit data bus, 5-bit address bus, read strobe, and write strobe. The 24-register set includes two command registers, in addition to scan-data FIFOs, configuration registers, status registers, and counter registers.

The host interface of the eTBC consists of an 8-bit data bus, 3-bit address bus, read/write select and read/write strobe. The 8-register set includes one command register in addition to scan-data FIFOs, configuration registers, status register, and counter register.

#### *IEEE Std 1149.1 Interface*

The TBC implements six separate TMS output signals allowing it to directly master up to six separate star-configured scan paths. The TBC also has two separate TDI inputs that can be used to support scan paths with different requirements for buffering of their TDO signals (for example, scan path(s) that are on the same PCB as the TBC versus scan path(s), which are on remote PCBs).

The eTBC implements a single set of TAP-mastering outputs, allowing it to directly master only one scan path. However, the eTBC provides a wealth of features that provide exceptional flexibility in control of scan test operations:

- Programmable division of TCK output frequency allows support for slow-scan-rate components while still operating fast-scan-rate components at higher speed.
- Discrete mode of TAP control enables arbitrary TMS/TDO sequences to allow for support of non-compliant components or specialized test extensions.
- Gated mode of TCK output provides mechanism for directly supporting 'ABT8996 Addressable Scan Port (ASP) shadow protocols in multidrop configurations.



### *Command Set*

Both TBC and eTBC devices support high-level command sets that allow the host to directly request IEEE Std 1149.1 state changes, scan operations, or periods of execution in the Run-Test/Idle state.

While the TBC can be made to generate ASP shadow protocols by proper sequencing of configuration changes and scan operations, the eTBC command set contains direct ASP scan commands.

### *Isolating the TBC From the IEEE Std 1149.1 Bus*

Each of the TBC and eTBC devices provides a mechanism for allowing its IEEE Std 1149.1 interface to be disabled. When the TOFF\* of the TBC is asserted or the OE\* of the eTBC is released, the respective TAP-mastering outputs are forced to a high-impedance state. By so disabling the IEEE Std 1149.1 interface, an external controller (for example, a scan-based ATE) is allowed to take control over the embedded scan path.

### *Host Requirements*

A host processor executing embedded test software (for example, Scan Engine) needs three primary hardware resources:

- Memory- (or I/O-) mapped parallel access to the TBC/eTBC
- ROM/EPROM space for the object code
- RAM or ROM space for the test vectors. These test vectors are broken into two primary blocks, stimulus data and response data.

It should be noted that the stimulus data could either be downloaded into RAM or be permanently programmed into ROM/EPROM.

### **Summary**

The SN74ACT8990 Test-Bus Controller and SN74LVT8980 Embedded Test-Bus Controller devices offer the designer of high-reliability equipment a way to embed automatic IEEE Std 1149.1-compliant test circuitry into products. Scan Engine software provides an easy way to control the TBC in

an embedded system. The solution discussed here maintains IEEE Std 1149.1-compatibility and access to test vectors developed during design verification. The result is continuous quality assurance with direct traceability to development data.

### **Boundary-Scan Test Flow**

When new ASICs or boards come from the manufacturing line, the first concern is that the devices work as designed. High-density ASICs and multi-layer PWBs with surface mount devices cannot be adequately tested without boundary-scan testing.

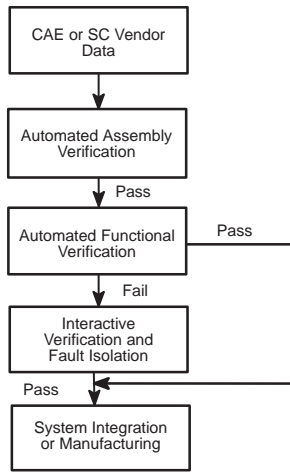
#### ***Solution***

Use boundary-scan techniques and tools on products designed with IEEE Std 1149.1-1990-compatible components.

#### ***Detailed Description***

Figure 7-16 summarizes an efficient verification process using BSDL supplied by manufacturers of IEEE Std 1149.1-compatible ICs and HSDL developed for the ASICs and PWB.

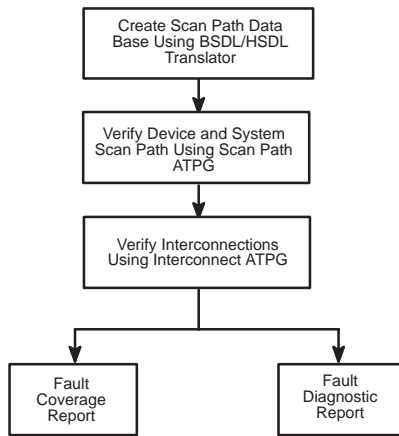




**Figure 7-16. General Boundary-Scan Test**

*Automated Assembly Verification*

Automated assembly verification depends on getting BSDL or HSDL descriptions for IEEE Std 1149.1-compatible devices from the manufacturer and developing corresponding HSDL for modules, boards, and systems. Figure 7-17 shows the flow that verifies a correct scan path and interconnections between boundary-scan cells.

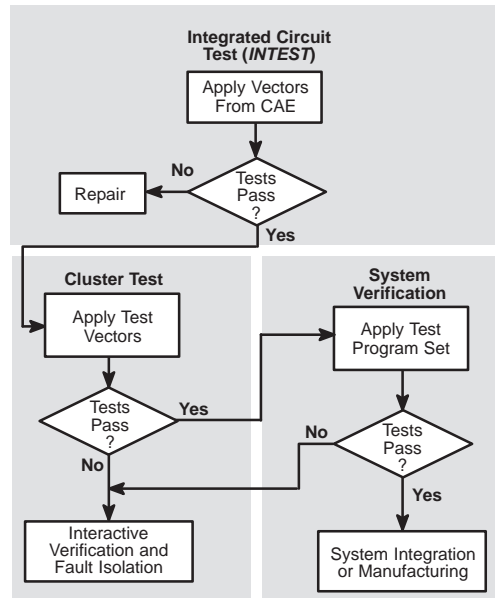


**Figure 7-17. Assembly Verification Flow**

Devices that pass assembly verification must then be tested for functionality.

*Automated Functional Verification and Fault Detection*

Functional verification begins with IC testing, followed by virtual component or cluster testing and system verification. These flows and the tools involved are shown in Figure 7-18.



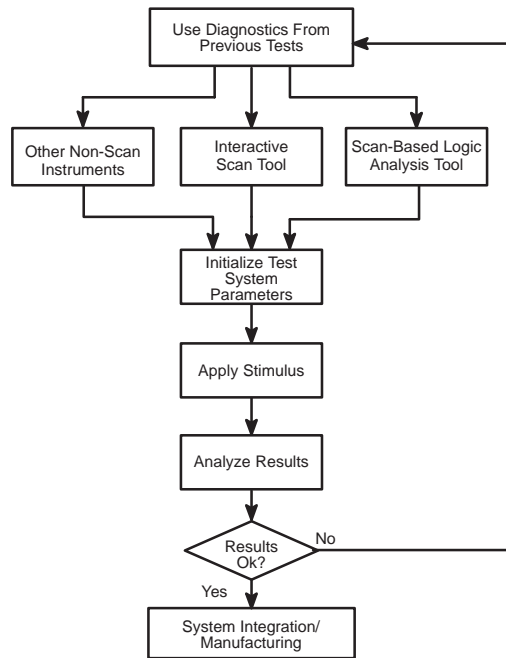
**Figure 7-18. Automated Functional Verification and Fault Detection**

No matter which flow is used, the goal is to reuse data whenever possible. For functional verification we want to reuse any serial or parallel vectors developed in the CAE system; those vectors become a pass/fail test. When CAE vectors are not available, boundary-scan test tools support test stimulus development approaches such as vector recording, macros, and high-level-language programs.

All functional tests highlight failures down to the vector level. Knowing which vector failed can reduce the time spent in interactive testing to isolate the problem to a device, register, or pin.

*Interactive Verification and Fault Isolation*

Figure 7-19 shows how faults in units failing previous tests can be isolated using scan-based test tools.



**Figure 7-19. Interactive Verification and Fault Isolation**

**Summary**

Design verification and fault isolation processes are greatly enhanced when a full suite of boundary-scan tools and techniques are used.



## Chapter 8 Product Summary

This chapter provides a brief description of TI's comprehensive offering of IEEE Std 1149.1-compatible components and a listing of TI's IEEE Std 1149.1 (JTAG) boundary-scan logic product family.

### **IEEE Std 1149.1-Compatible Components**

TI has a long history of involvement with JTAG and IEEE Std 1149.1 and of support for integrated circuits that incorporate IEEE Std 1149.1-compatible boundary scan. Starting with release of the first commercially available boundary-scan logic ICs in May 1990, only 3 months after ratification of IEEE Std 1149.1, TI has lead the semiconductor industry in its offerings of products that support board- and system-level testability.

In addition to TI's broad line of boundary-scan logic devices (see below), which are implemented primarily for the purpose of building board- and system-level test architectures, TI supports IEEE Std 1149.1-compatible ICs across its broad product lines. From ASIC to DSP, networking to multimedia, TI's portfolio includes many boundary-scan devices.

### **Highlights**

**ASIC** — To facilitate the implementation of IEEE Std 1149.1-compliant boundary scan in TI's ASIC products, boundary-scan-cell modules have been developed for CMOS standard-cell and gate-array libraries.

**DSP** — Select functions in TI's 'C4x, 'C5x, 'C54x, and 'C8x (MVP) generations incorporate IEEE Std 1149.1 boundary scan. In addition, all functions in these generations and in the 'C2xx generation use the test access port (TAP), as specified by IEEE Std 1149.1, to access on-chip emulation features.

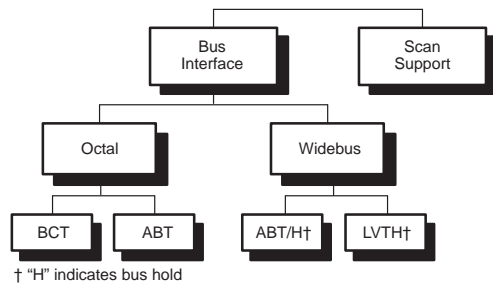
**Networking** — Currently, several functions from ThunderLAN™ (Ethernet™) and ThunderCELL™ (Asynchronous Transfer Mode) families offer IEEE Std 1149.1 boundary scan.

### IEEE Std 1149.1 (JTAG) Boundary-Scan Logic

TI's family of IEEE Std 1149.1 (JTAG) boundary-scan logic includes octal bus interface, Widebus™, and scan-support functions that incorporate circuitry that allows them, and the electronic systems or subsystems in which they are used, to be tested without reliance on traditional probing techniques.

In all, over 30 devices, composed of a wide selection of BCT and ABT octal bus interface, ABT(H) and LVTH Widebus™, and scan-support functions, are currently available.

For data sheets and documentation, see the *1997 Boundary-Scan Logic, IEEE Std 1149.1 (JTAG) 5-V and 3.3-V Bus-Interface and Scan-Support Products Data Book*, literature number SCTD002.



**Figure 8-1. TI's Family of IEEE Std 1149.1 (JTAG) Boundary-Scan Logic**

### **Bus Interface**

Bus-interface functions are available in BCT, ABT, and LVT (3.3-V ABT) technologies, in octal and Widebus™ (18- and 20-bit) options of standard buffers, latches, flip-flops, transceivers, and registered transceivers. Featured is the universal bus transceiver (UBT™) which, in a single package, can serve all of these common bus-interface roles. In addition, ABT and LVT technologies offer devices with bus-hold inputs and integrated series-damping resistors. Package options for the bus-interface devices include plastic dual in-line (PDIP), small-outline integrated circuit (SOIC), shrink small-outline package (SSOP), thin shrink small-outline package (TSSOP), and plastic thin quad flat package (TQFP).

#### *Octal Bus Interface*

SN74BCT8240A	24	Octal Inverting Buffer/ Driver
SN74BCT8244A	24	Octal Buffer/ Driver
SN74BCT8245A	24	Octal Bus Transceiver
SN74BCT8373A	24	Octal Transparent D-Type Latch
SN74BCT8374A	24	Octal D-Type Flip-Flop
SN74ABT8245	24	Octal Bus Transceiver
SN74ABT8543	28	Octal Registered Bus Transceiver
SN74ABT8646	28	Octal Registered Bus Transceiver
SN74ABT8652	28	Octal Registered Bus Transceiver
SN74ABT8952	28	Octal Registered Bus Transceiver

#### *Widebus™ — TQFP*

SN74ABT18502	64	18-Bit Universal Bus Transceiver
SN74ABT18504	64	20-Bit Universal Bus Transceiver
SN74ABT18646	64	18-Bit Registered Bus Transceiver
SN74ABT18652	64	18-Bit Registered Bus Transceiver
SN74ABTH18502A	64	18-Bit Universal Bus Transceiver
SN74ABTH18504A	64	20-Bit Universal Bus Transceiver
SN74ABTH18646A	64	18-Bit Registered Bus Transceiver
SN74ABTH18652A	64	18-Bit Registered Bus Transceiver
SN74LVT18502	64	18-Bit Universal Bus Transceiver
SN74LVTH18502A	64	18-Bit Universal Bus Transceiver
SN74LVTH18504A	64	20-Bit Universal Bus Transceiver
SN74LVTH18646A	64	18-Bit Registered Bus Transceiver
SN74LVTH18652A	64	18-Bit Registered Bus Transceiver

*Widebus™ — TQFP, with series-damping resistors*

SN74ABTH182502A	64	18-Bit Universal Bus Transceiver
SN74ABTH182504A	64	20-Bit Universal Bus Transceiver
SN74ABTH182646A	64	18-Bit Registered Bus Transceiver
SN74ABTH182652A	64	18-Bit Registered Bus Transceiver
SN74LVT182502	64	18-Bit Universal Bus Transceiver
SN74LVTH182502A	64	18-Bit Universal Bus Transceiver
SN74LVTH182504A	64	20-Bit Universal Bus Transceiver
SN74LVTH182646A	64	18-Bit Registered Bus Transceiver
SN74LVTH182652A	64	18-Bit Registered Bus Transceiver

*Widebus™ — TSSOP*

SN74ABT18245A	56	18-Bit Bus Transceiver
SN74ABT18640	56	18-Bit Inverting Bus Transceiver
SN74LVTH18245	56	18-Bit Bus Transceiver
SN74LVTH18512	64	18-Bit Universal Bus Transceiver
SN74LVTH18514	64	20-Bit Universal Bus Transceiver
SN74LVTH18516	64	18-Bit Universal Bus Transceiver
SN74LVTH18640	56	18-Bit Inverting Bus Transceiver

*Widebus™ — TSSOP, with series-damping resistors*

SN74LVTH182245	56	18-Bit Bus Transceiver
SN74LVTH182512	64	18-Bit Universal Bus Transceiver
SN74LVTH182514	64	20-Bit Universal Bus Transceiver
SN74LVTH182516	64	18-Bit Universal Bus Transceiver
SN74LVTH182640	56	18-Bit Inverting Bus Transceiver

**Universal Bus Transceiver (UBT™)**

The UBT is the flagship of TI's IEEE Std 1149.1 bus-interface offerings. With its dual-ranked latch storage and generalized control logic, the basic UBT can perform all of the most common bus-interface roles: driver, latch, flip-flop, transceiver, latched transceiver, and registered transceiver. Enhanced UBT functions offer additional features such as clock enable and stored/real-time data multiplexers. With the added feature of boundary scan, TI's IEEE Std 1149.1 UBTs are the ideal solution for nearly all bus-interface needs.



**Table 8-1. IEEE Std 1149.1 UBTs Replace 50+ Bus Functions**

FUNCTION	8 BIT	9 BIT	10 BIT	16 BIT	18 BIT	20 BIT
Transceiver	'245,'623,'645	'863	'861	'16245,'16623	'16863	'16861
Buffer/Driver	'241,'244,'541		'827	'16241,'16244,'16541	'16825	'16827
Latched Transceiver	'543			'16543	'16472	
Latch	'373,'573	'843	'841	'16373	'16843	'16841
Registered Transceiver	'646,'652			'16646,'16652	'16474	
Flip-Flop	'374,'574		'821	'16374		'16821
Standard UBT*					'16500,'16501	
Universal Bus Driver					'16835	
*18502 and *18512 UBTs Replace Above Functions						
Registered Transceiver w/CLK Enable	'2952			'16470,'16952		
Flip-Flop w/CLK Enable	'377	'823			'16823	'16721
Std UBT* w/CLK Enable					'16600,'16601	
*18516 UBT Replaces Above Functions						
*18504 and *18514 UBTs Replace All Above Functions						

\*Non-Boundary-Scan Device

**Scan Support**

Scan-support functions facilitate implementation of board- and system-level test architectures. These include devices for mastering the IEEE Std 1149.1 test bus, adapting the IEEE Std 1149.1 test bus to multidrop configuration, performing at-speed functional test, and partitioning the scan path into smaller, more manageable segments.

SN74LVT8980	28	Embedded Test-Bus Controller
SN74ACT8990	44	Test-Bus Controller
SN74ABT8996	24	Addressable Scan Port
SN74ACT8994	28	Digital Bus Monitor
SN74ACT8997	28	Scan-Path Linker
SN74ACT8999	28	Scan-Path Selector

### *Test-Bus Controllers*

**Embedded Test-Bus Controller (eTBC)** — The SN74LVT8980 provides a simple, off-the-shelf solution that can be hosted by a low-cost 8-bit microcontroller or microprocessor to generate the signals required to master the IEEE Std 1149.1 test bus. Its LVT implementation means that this device is the industry's first test-bus solution to operate at 3.3 V, while it still interfaces to scan-path devices that use 5-V power.

**Test-Bus Controller (TBC)** — The SN74ACT8990 provides a simple, off-the-shelf solution that can be hosted by a 16-bit microcontroller/microprocessor to generate the signals required to master the IEEE Std 1149.1 test bus.

### *Backplane/Multidrop Test-Bus Support*

**Addressable Scan Port (ASP)** — IEEE Std 1149.1 defines how to implement boundary scan at the IC level but does not address board- or system-level architectures. With TI's SN74ABT8996 device, backplane or other multidrop applications now can be supported.

### *At-Speed Functional Test*

**Digital Bus Monitor (DBM)** — The SN74ACT8994 is a special-function device that provides the capability to emulate the functions of logic and signal analyzers. The DBM can be embedded in systems as a non-intrusive at-speed monitor. A single DBM monitors up to 16 signals, but several can be used in concert for width or depth expansion.

### *Scan-Path Support*


**Scan-Path Linker (SPL)** — The SN74ACT8997 provides for scan-path partitioning by allowing selection, under IEEE Std 1149.1 scan control, of any combination of up to four secondary scan paths. Multiple SPL devices can be cascaded to support any desired number of secondary scan paths, as well as multilevel hierarchies.

**Scan-Path Selector (SPS)** — The SN74ACT8999 provides for scan-path partitioning by allowing selection, under IEEE Std 1149.1 scan control, of any one of four secondary scan paths.

**Note:**

Not all devices mentioned are available at the time of this printing. Contact your TI sales representative or authorized distributor for commercial or military grade availability information.





## Chapter 9

### Other Support and Learning Products

This chapter provides information concerning learning tools available for IEEE Std 1149.1-1990.

#### Scan Educator

The Scan Educator PC-based tutorial software introduces the fundamentals of IEEE Std 1149.1, including architecture, protocols, and required instruction set. Self-paced and menu-driven, it contains both information and animated boundary-scan simulations. Hands-on exercises guide you through a boundary-scan test of an IEEE Std 1149.1-compliant octal at the bit-by-bit and register levels. You also are shown how to use boundary-scan testing with single or multiple devices for in-circuit observability and controllability.

#### Scan Board

No matter where you are on the boundary-scan learning curve, TI's Scan Board can help you move to higher levels of understanding — quickly and easily. Scan Board can be a learning tool for new users of boundary-scan and a test and evaluation platform for the experienced user. This specially developed board comes with multiple IEEE Std 1149.1-compliant devices that can help you evaluate both the tools and the concepts behind board-level testing. With Scan Board, you can perform boundary-scan interconnect tests and insert various faults and fault types, as well as demonstrate board-level built-in self-test (BIST) for testing memory, internal test (*INTEST*) of an ASIC, internal BIST of an ASIC, cluster testing, single- and multiple-scan paths, and many other capabilities. Scan Board comes with schematics, netlists, X-Y plots, data sheets, test patterns, BSDL descriptions, and a *free* executable software program. This software allows you to apply test patterns supplied with Scan Board, or to apply your own.

Scan Board demonstrates these advanced test techniques and more:

- Scan-path verification
- Interconnect testing
- Pins-in (IC core logic) testing
- BIST methods at the device and board level
- Boundary-scan interconnect automatic test-pattern generation (ATPG)
- Functional cluster logic tests using boundary-scan and BIST capabilities
- Fault detection and isolation
- Control and monitoring of discrete event lines
- Counting, toggle, and pseudorandom pattern generation (PRPG) stimulus methods
- Parallel signature analysis (PSA) response capture
- Scan-path switching

#### ***Flexibility***

Scan Board incorporates basic boundary-scan features for new users to learn boundary-scan testing, and also incorporates advanced extensions such as BIST, *INTEST*, internal scan, and multiple scan paths for advanced users. Scan Board's physical layout separates independent multiple functions both electrically and physically, while maintaining a single continuous IEEE Std 1149.1 scan path for ease of test manipulation. Fault-injection switches are provided so the user can practice fault-isolation techniques. Scan Board provides for the injection of 12 different faults. Fault types include: stuck-at-one, stuck-at-zero, bridging, non-adjacent bridging, internal device, and scan path.



### **Compatibility**

Scan Board is compatible with in-circuit test fixtures and testers. Nodes are accessible via boundary-scan or from the bottom with adequate and uniform spacing for in-circuit probes. Nets without both the boundary-scan driver and receiver are accessible via 40-mil probe points with 100-mil spacing.

### **Supporting Documentation Included**

Scan Board comes with board description and operation, schematics and diagrams, X-Y and Gerber plots, a fault table, and boundary-scan device data sheets. Electronic files include BSDL, HSDL, Netlists (Viewlogic, EDIF 2.0.0, and Teradyne CDB), interconnect patterns (SVF), ASIC internal test patterns (SVF), and cluster-logic test patterns (SVF). Scan Board demonstration software is included at no extra charge.

### **CD-ROM**

TI has combined the key elements of IEEE Std 1149.1 on a single CD-ROM. Now the latest versions of the IEEE Std 1149.1-1990 (including IEEE Std 1149.1a-1993) are merged into one searchable document.

Also included are TI's:

- Test-bus evaluation report
- Application notes
- Data sheets for TI boundary-scan products

The test-bus evaluation (TBE) report was written by TI's Defense Systems & Electronics Group to evaluate the applications and impact of standard test buses on overall system testability. The TBE report is based on years of test-bus development and applications experience at TI; since the early 1980s, TI has played a key role in defining test buses, first, for the VHSIC program, and then later as a key contributor in both JTAG and IEEE Std 1149.1.

This CD-ROM brings together current information on IEEE Std 1149.1. Microsoft and UNIX environments are supported.





## Appendix A

### Abbreviations/Acronyms

<b>AC</b>	Alternating Current (dynamic)
<b>ASIC</b>	Application-Specific Integrated Circuit
<b>ASP</b>	Addressable Scan Port
<b>ASSET</b>	Advanced Support System for Emulation and Test
<b>ATE</b>	Automatic Test Equipment
<b>ATG</b>	Automatic Test Generation
<b>ATPG</b>	Automatic Test-Pattern Generation
<b>BIST</b>	Built-In Self-Test
<b>BIT</b>	Built-In Test
<b>B/S</b>	Boundary Scan
<b>BSC</b>	Boundary-Scan Cell
<b>BSDL</b>	Boundary-Scan Description Language
<b>BSR</b>	Boundary-Scan Register
<b>BST</b>	Boundary-Scan Test
<b>CAD</b>	Computer-Aided Design
<b>CAE</b>	Computer-Aided Engineering
<b>DBM</b>	Digital Bus Monitor
<b>DC</b>	Direct Current (static)
<b>DFT</b>	Design for Test
<b>DIP</b>	Dual In-Line Package
<b>DR</b>	Data Register
<b>DSP</b>	Digital Signal Processor
<b>EDA</b>	Electronic Design Automation
<b>ESD</b>	Electrostatic Discharge
<b>ETBC</b>	Embedded Test-Bus Controller
<b>FIFO</b>	First-In, First-Out (memory)
<b>HDL</b>	Hardware Description Language
<b>HSDL</b>	Hierarchical Scan Description Language
<b>IC</b>	Integrated Circuit
<b>ICE</b>	In-Circuit Emulation
<b>ICT</b>	In-Circuit Test
<b>ID</b>	Identification
<b>IEEE</b>	Institute of Electrical and Electronics Engineers
<b>I/O</b>	Input/Output

<b>IR</b>	Instruction Register
<b>ISP</b>	In-System Programming
<b>JEDEC</b>	Joint Electronic Device Engineering Council
<b>JIT</b>	Just-In-Time (manufacturing)
<b>JTAG</b>	Joint Test Action Group
<b>LSB</b>	Least-Significant Bit
<b>LSSD</b>	Level-Sensitive Scan Design
<b>MSB</b>	Most-Significant Bit
<b>PCB</b>	Printed Circuit Board
<b>PPM</b>	Parts Per Million
<b>PRPG</b>	Pseudorandom Pattern Generation
<b>PSA</b>	Parallel Signature Analysis
<b>PWB</b>	Printed Wiring Board
<b>SPL</b>	Scan-Path Linker
<b>SPS</b>	Scan-Path Selector
<b>SSA</b>	Serial Signature Analysis
<b>SVF</b>	Serial Vector Format
<b>TAP</b>	Test Access Port
<b>TBC</b>	Test-Bus Controller
<b>TCK</b>	Test Clock
<b>TDI</b>	Test Data Input
<b>TDL</b>	Test Description Language
<b>TDO</b>	Test Data Output
<b>TMS</b>	Test Mode Select
<b>TPS</b>	Test Program Set
<b>UBT</b>	Universal Bus Transceiver
<b>UUT</b>	Unit Under Test
<b>VHDL</b>	VHSIC Hardware Description Language
<b>VHSIC</b>	Very High-Speed Integrated Circuit
<b>XCVR</b>	Transceiver

## Appendix B Glossary

### **Automatic Test Generation**

A functional test pattern generation that is done algorithmically on a computer

### **Boundary-Scan Description Language (BSDL)**

A hardware description language developed to describe devices built to IEEE Std 1149.1. See also HSDL.

### **Built-In Self Test**

Logic included within a design that can apply test signals and compare results to determine if the design is working correctly

### **Concurrent Fault Simulation**

A fault simulation method that simulates only fault models that differ from the fault-free model at the node being simulated. The node being simulated is an event-driven node.

### **Controllability**

The ability to set a logical value on a signal node within the design. Controllability can be a measure of how difficult it is to generate test patterns. If a signal is hard to control, it is difficult to set up values necessary to test design features.

### **Design for Test**

A method that incorporates rules and techniques in the design process to make testing easier

### **Detectable Fault**

A possible failure that has at least one test pattern or sequence of patterns that, when applied to a device, detect failure

### **Deterministic Test Vectors**

A fixed-order set of test patterns

### **Fault**

A design failure or flaw that causes an incorrect response to input stimuli

### **Fault Grade**

The percentage of modeled faults that will be detected by a test sequence when applied to a device. The fault grade is determined through fault simulation.

**Fault Model**

A simulator representation of a fault to model an unexpected behavior of a failure

**Fault Simulation**

The process of simulating test patterns using fault models and a fault-free model to determine whether potential failures will be detected with the test sequence

**Gate-Pin Fault**

A fault modeled at the connection of a gate pin to the signal-node net

**Hierarchical Scan Description Language (HSDL)**

A superset of BSDL developed by TI. HSDL is used to describe IEEE Std 1149.1-compliant devices, modules, and systems. See also BSDL.

**Initialization**

The process of placing a circuit or unit under test into a known state for testing or logic simulation

**Interconnect Testing**

A test process that verifies correct connections between ICs and modules on a board

**Level-Sensitive Scan Design (LSSD)**

The IBM DFT methodology of scan design. "Level Sensitive" means that all registers are activated with voltage levels rather than clock edges.

**Linear Feedback Shift Register (LFSR)**

A shift register counter that can be used for pseudorandom test pattern generation and for compression of test pattern results

**Load Fault**

A fault model that is a load on a wired junction

**Logical Redundancy**

Design logic that, removed from the design, performs and provides the same static logic responses. Logical redundancy may be purposefully added to improve speed or drive performance.

**Modular Testing**

Testing a design by applying independent test sequences to test isolatable modules. Each module has its own test sequence that is not affected by other modules in the design. With modular testing, ATG and fault grading can be performed on a single module at a time.

**Multiple Fault**

A fault model created by simultaneously representing the fault with multiple stuck-at faults

**Node Fault**

A fault model that ties an interconnection net to a fixed logic level. A node fault is equivalent to all sources on a net being source faults with the same logical value.

**Observability**

The capability to observe the effect of a node value at an output pin. If the node value changes, the output value also changes.

**Parallel Fault Simulation**

A method that simulates a set of fault models at the same time as the fault-free model

**Parallel Signature Analyzer**

An LFSR used to compress test data by collecting data from the design and exclusive ORing the resulting test data with register-state data

**Parametric Test**

A test that checks the voltage, current, and timing specifications of a design. The ac and dc propagation tests are parametric tests.

**Propagation**

The response of an output of a gate (or net) to an input of the gate (or net)

**Scan-Path Design**

A DFT methodology where all or a selected group of storage elements can be serially interconnected to facilitate testing of embedded combinational logic in an integrated circuit

**Scan-Path Linker (SPL)**

TI's SN74ACT8997 device acts as a scan-path multiplexer, allowing dynamic path switching. The SPL can select any combination of four secondary scan paths.

**Scan-Path Selector (SPS)**

TI's SN74ACT8999 device acts as a scan-path multiplexer, allowing dynamic path switching. The SPS can select one of four secondary scan paths at a time.

**Scan Testing**

The DFT technique that connects all internal registers in a design into a shift register used during test. The scan shift registers, called scan paths, are used to load any desirable state before application of a test over combinational logic between serial (scannable) register latches and unload any resultant state for observation.

**Serial Vector Format (SVF)**

A standard ASCII-based pattern format for expressing IEEE Std 1149.1 scan operations and state transitions. This vector format was jointly developed by TI and Teradyne to allow pattern transportability between test tools.

**Source Fault**

A fault model that is a source to a wired-junction net. Gate outputs are examples of source faults.

**Stuck Closed (Shorted Gate) Fault**

A stuck-at fault model in which the transistor controlled by the gate is always closed. This has the same effect as shorted data lines. This fault model is the same as an SA1 fault on the gate input of an n-p-n transistor or an SA0 fault on the gate input of a p-n-p transistor.

**Stuck Fault**

A failure model in which a gate pin is modeled as stuck to VCC (for stuck-at-one, SA1 ) or to GND (for stuck-at-zero, SA0)

**Stuck Open (Open Gate) Fault**

A stuck-fault model in which the transistor controlled by the gate is always open. This fault model is the same as an SA0 fault on the gate input of an n-p-n transistor or an SA1 fault on the gate input of a p-n-p transistor.

**Test Access Port (TAP)**

Port described in IEEE Std 1149.1-1990. Must contain a minimum of three input connections (TDI, TMS, TCK) and one output connection (TDO). A fourth input connection (TRST\*) is optional. The TAP provides access to test functions built into a component.

**Test Description Language (TDL)**

A test pattern format that describes the stimuli and expected results for a test application. TDL tests are applied using I/O connector pins.

**Test Generation**

The process of producing a test sequence to test a design. Three methods of test generation are: automatic test generation (ATG), manual test preparation, and random input values generation.

**Test Pattern**

A set of input stimuli values that are applied at the beginning of a period of time and a set of output observation values made at the end of a period of time that are represented by a string of values

**Test Pattern Grading**

The process of fault simulating a test pattern sequence to obtain a fault grade

**Test Point Insertion**

The DFT technique that includes additional connections to internal nodes for either control or state observation

**Test Vector**

Another name for a test pattern

**Testability**

The property of a circuit, board, or system that enables testing

**Undetectable Fault**

A fault that cannot be detected by any achievable test pattern. Undetectability may be due to logic redundancy or to logic that cannot be observed.

**Unpredictable Fault**

A fault that causes the value of a node to be indeterminate, thereby making it impossible to detect a fault



B-6

*Glossary*





## Appendix C References

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## Appendix D Internet Starting Points

Institute of Electrical and Electronics Engineers (IEEE)  
<http://www.ieee.org/index.html>

IEEE Std 1149.1  
<http://www.computer.org/tab/ttc/standard/s1149-1/home.html>

Test Technology Technical Committee (sponsor for IEEE 1149.x standards)  
<http://www.computer.org/tab/ttc/>

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<http://www.ti.com>

Texas Instruments Semiconductor Group  
<http://www.ti.com/sc/docs/schome.htm>

Texas Instruments Advanced System Logic  
<http://www.ti.com/sc/docs/asl/home.htm>

Texas Instruments IEEE 1149.1 (JTAG) Boundary Scan  
<http://www.ti.com/sc/docs/jtag/jtaghome.htm>

Texas Instruments IEEE 1149.1 Silicon Product and BSDL Availability  
<http://www.ti.com/sc/docs/jtag/silicon.htm>

Texas Instruments Product Information Data Sheet Search  
<http://www.ti.com/sc/docs/psheets/pids.htm>



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